

Building Confidence in Open IC Design

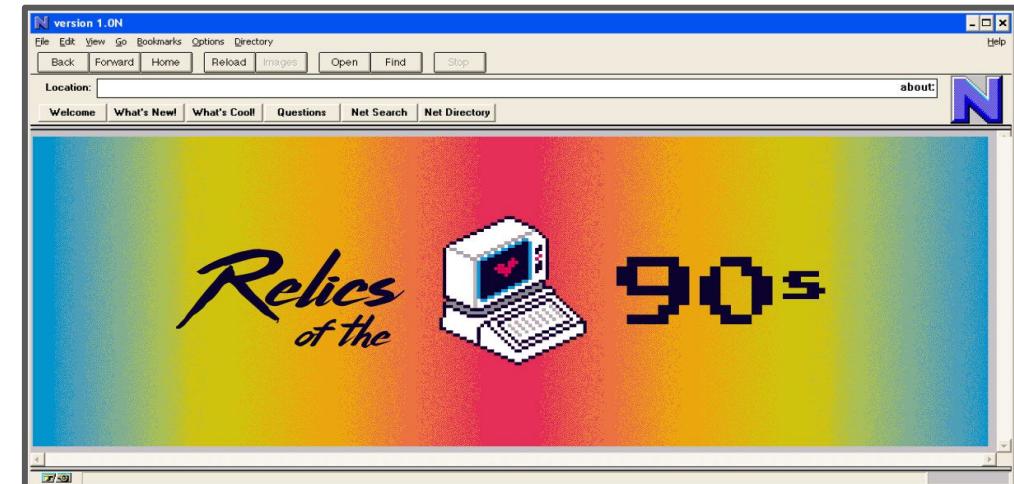
Using OpenFASOC

Mehdi Saligane
University of Michigan
mehdi@umich.edu

7th July, 2023

Evolution of Software Dev

- Software Dev in the 90s
 - Vendor provided compiler
 - Toolchain incompatibilities
 - OS dependent



Context and Background

- Software Dev in the 90s
 - Vendor provided compiler
 - Toolchain incompatibilities
 - OS dependent

Looks like current
hardware dev!

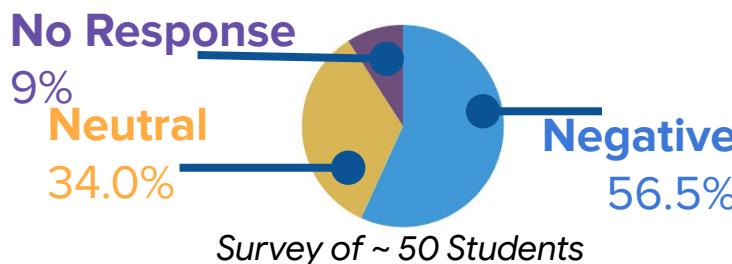


Lowering Costs & Barriers to Chip Design

- Software Dev in the 90s
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*Describe your experience with
(tapeout) toolchain in one word*

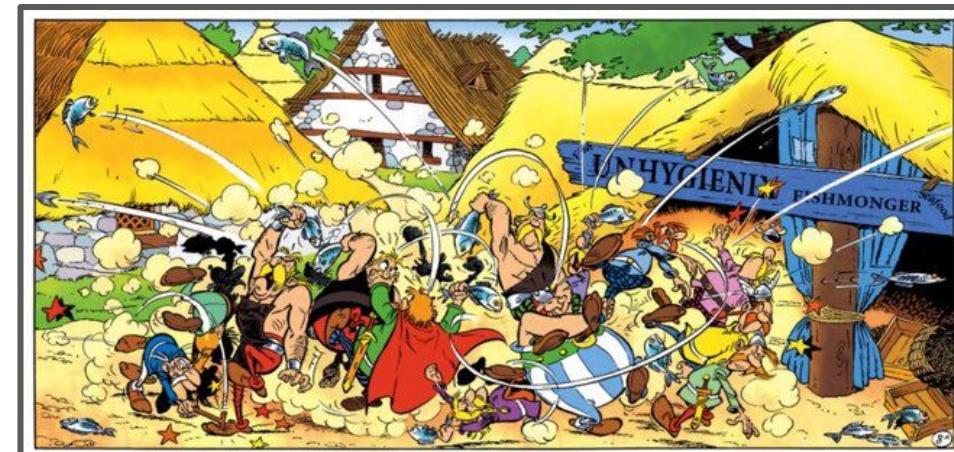
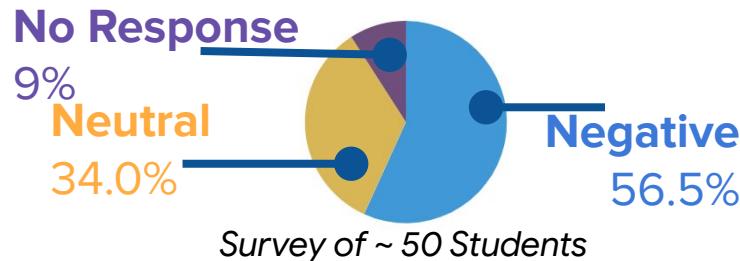


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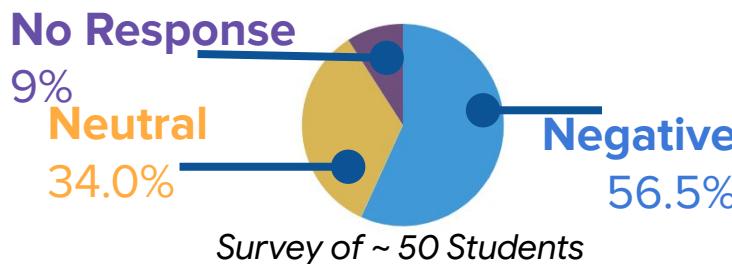
Lowering Costs & Barriers to Chip Design

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70 000 HW vs 830 000 SW
Eng.

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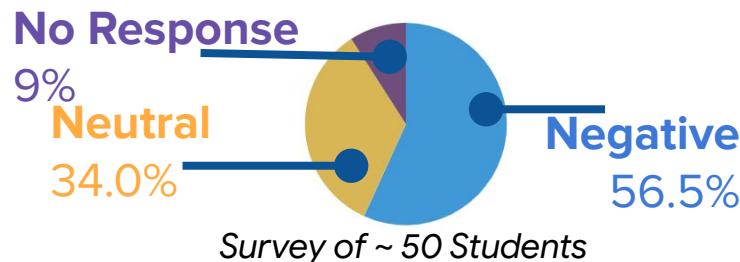


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(tapeout) toolchain in one word**



UG student Ali Hammoud to present his winning
Code-a-Chip design at ISSCC 2023

Catharine June • February 16, 2023



Hammoud's project is based on the open-source hardware design tool called OpenFASoC, developed at Michigan.



Ali Hammoud, a second-year student in computer engineering, is a winner in the inaugural international Code-a-Chip competition. He will present his project in open-source chip design at the [2023 International Solid-State Circuits Conference](#) (ISSCC), along with 6 other design teams from around the world. His design is called [OpenFASoC: Digital LDO Generator](#).

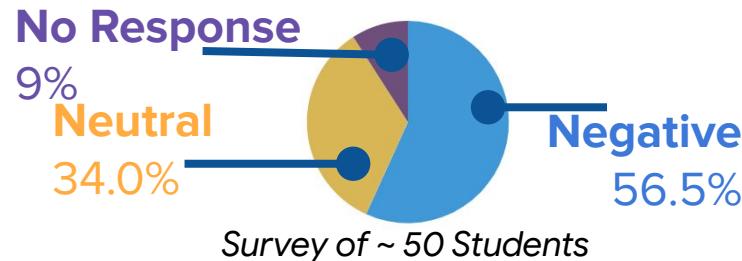
Hammoud's design is based on the open-source tool called [OpenFASoC](#), short for Open-Source Fully Autonomous System-on-Chip, which was co-developed by his faculty advisor on the project, Dr. Mehdi Saligane. OpenFASoC was developed for analog circuit design, which is more difficult to automate than digital circuit design.

Lowering Costs & Barriers to Chip Design

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*Describe your experience with
(tapeout) toolchain in one word*



Hardware

New deploy 18 months

New Deploy

18 months

All Replaced

~6 years

~4 versions deployed

Software

Push once a week

Normal Push

4-6 hours

Emergency Push

<1 hours

~1 version deployed

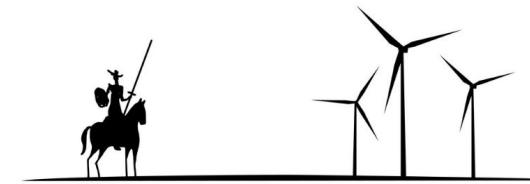
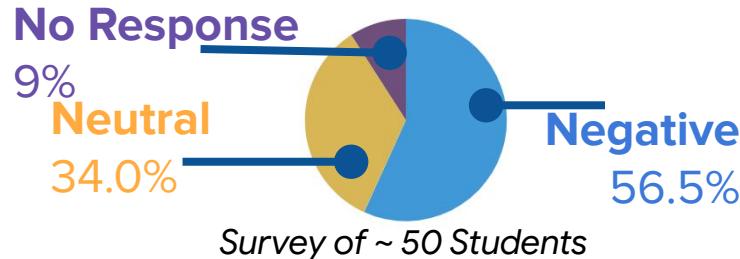
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Lowering Costs & Barriers to Chip Design

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Is Hardware Development
Broken?

Hardware

New deploy 18 months

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All Replaced

~6 years

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Software

Push once a week

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4-6 hours

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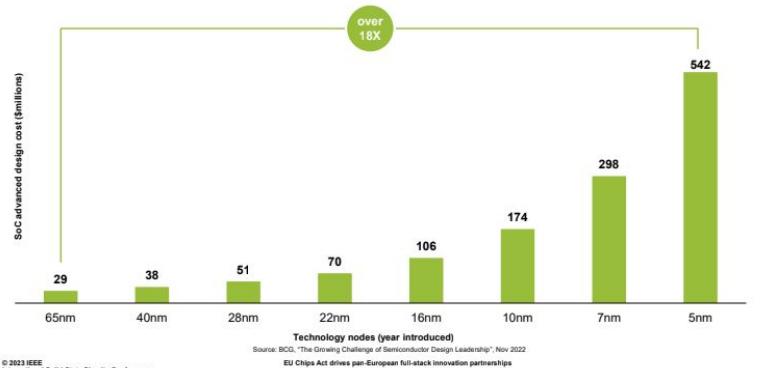
<1 hours

~1 version deployed

Lowering Costs & Barriers to Chip Design

- Is Hardware Development Broken?

Design costs rising with every new technology node



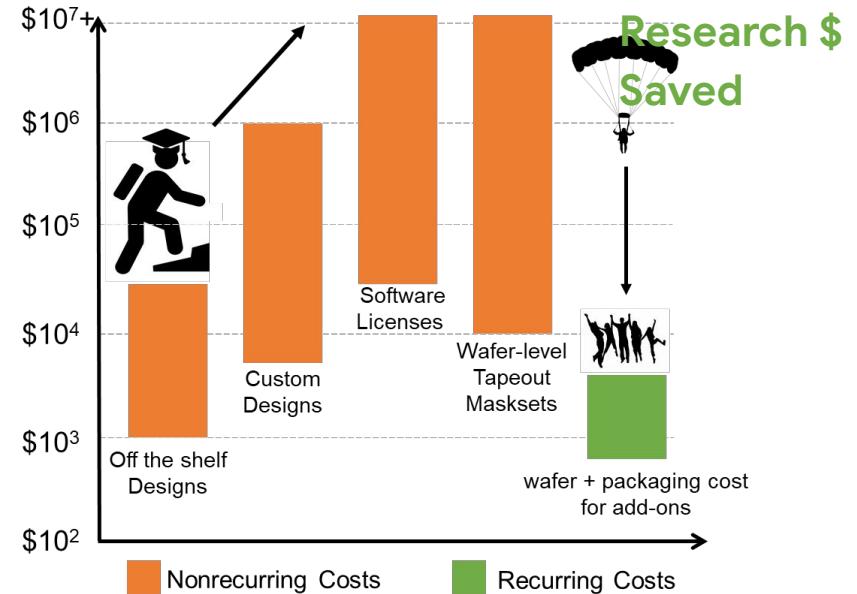
The Missing Pieces of Open Design Enablement: A Recent History of Google Efforts

Invited Paper

Tim Ansell
tansell@google.com
Google
Mountain View, California

Mehdi Saligane
mehdi@umich.edu
University of Michigan
Ann Arbor, Michigan

- T. Ansell and M. Saligane, "The Missing Pieces of Open Design Enablement: A Recent History of Google Efforts : Invited Paper," 2020 IEEE/ACM International Conference On Computer Aided Design (ICCAD), San Diego,



Source: NIST

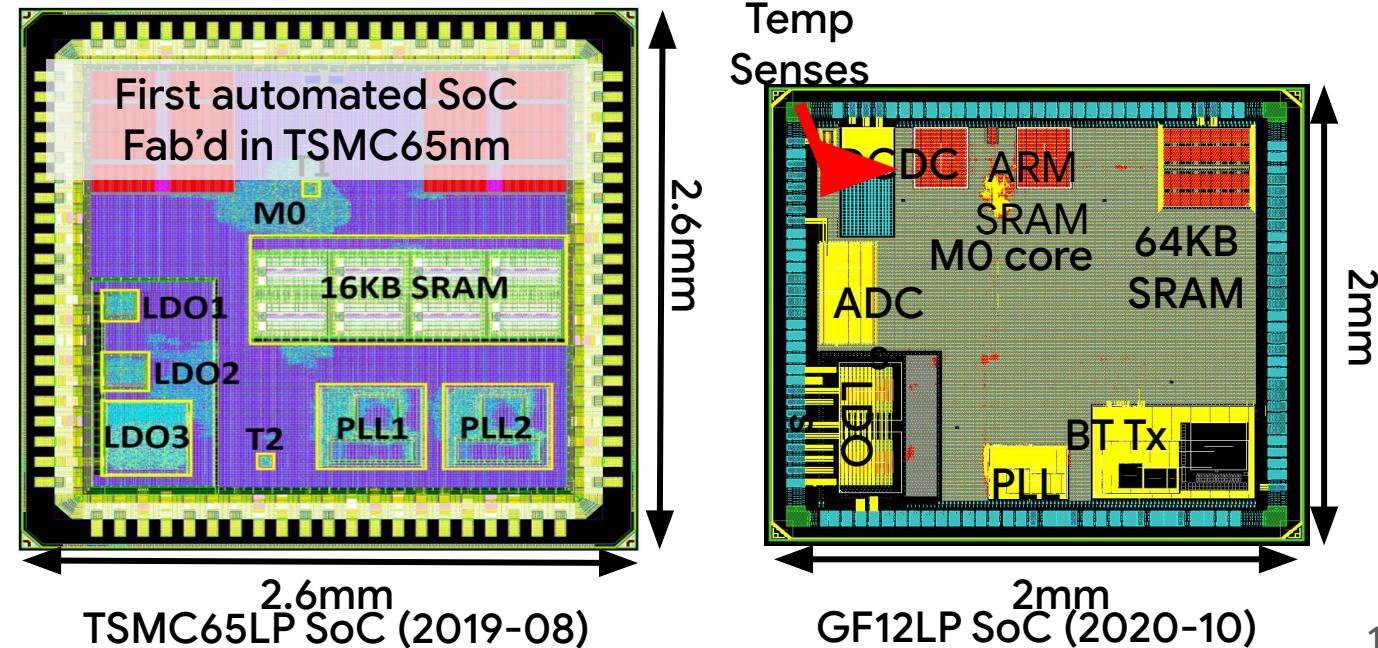
Overview of FASOC

Fully Autonomous SoC Synthesis

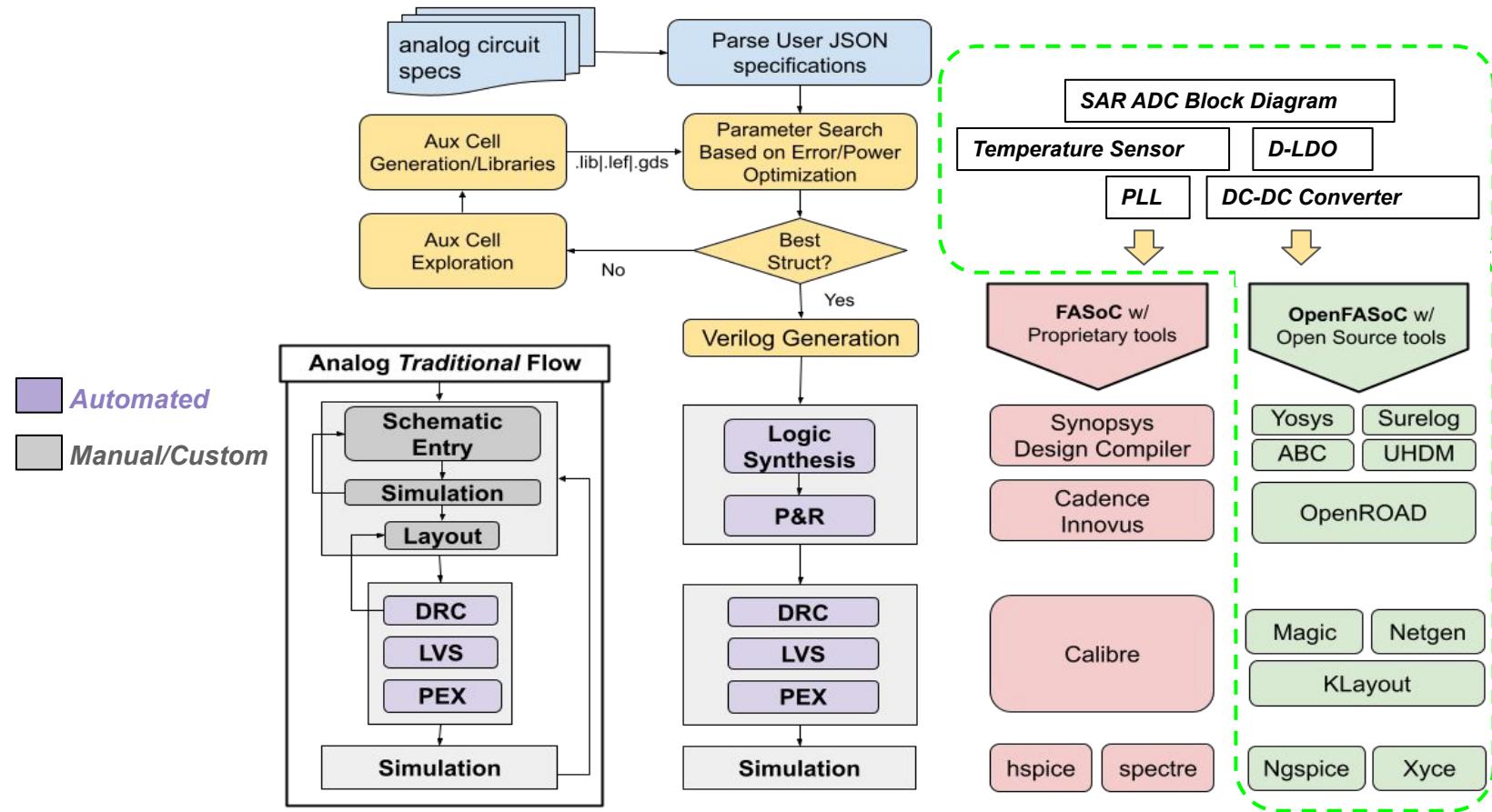
- DARPA IDEA Program (OpenROAD and FASoC)
- Multi-University and Industry effort
- Multiple tape-outs in TSMC 65, GF12LP, SkyWater 130nm



<https://fasoc.engin.umich.edu/>



Now proprietary or **open source** design flow



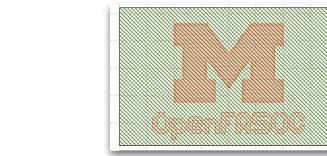
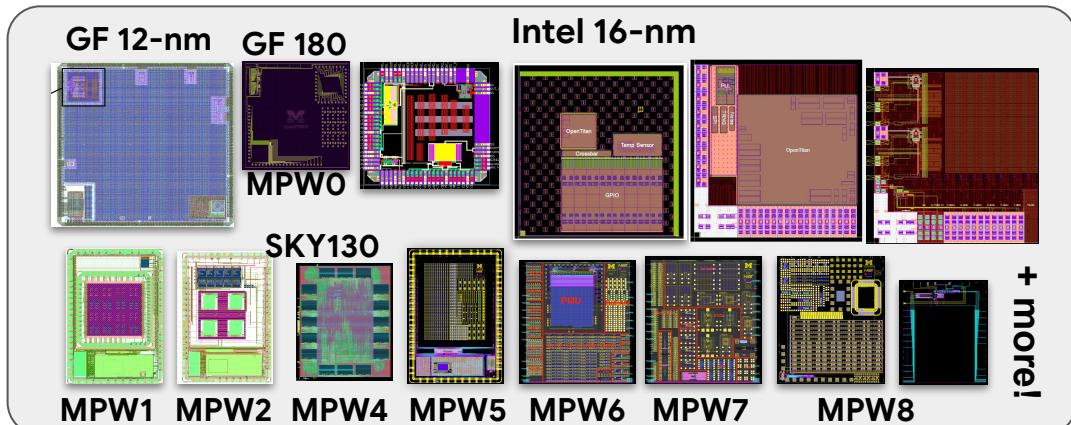
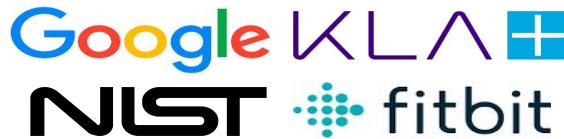
OpenFASoC!

**Automated
portable
analog**

Overview of OpenFASOC

Fully Autonomous SoC Synthesis

- DARPA IDEA Program, now funded by Google, NIST and others
- Multiple tape-outs in TSMC 65, GF12LP, SKY130, GF180MCU, Intel 16



openfasoc.readthedocs.io



[CHIPS Alliance Workshop](#)
[2021-11](#)



[OpenPOWER AI Workshop](#)
[IBM - 2022-11](#)



[CHIPS Alliance Technology Update](#)
[2022-12](#)

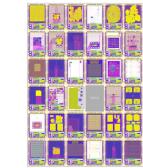


[RISC-V Alliance Japan](#)
[2022-12](#)

On-Going Projects & Contributions

Open-Source IC & tapeouts

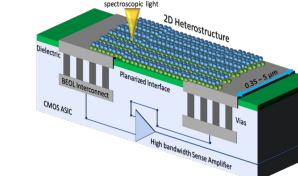
→ 1st *Open* Silicon Results



NIST Nanofabrication Accelerator

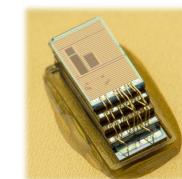
→ 1st *Open* Nanotechnology Platform

→ Cryogenic CMOS



Low-Power IC Design

→ *Rapid* Prototyping for Wearables



Hardware Security

→ 1st *Open* Root of Trust SoC



Automated & Open Nanotechnology Platform

CMOS Integration Critical for Measurements

- New devices and materials are continually proposed by the academic community

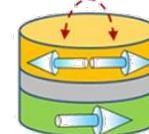
Resistive switching
memory (ReRAM)



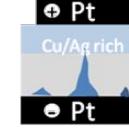
Phase Change Memory
(PCM)



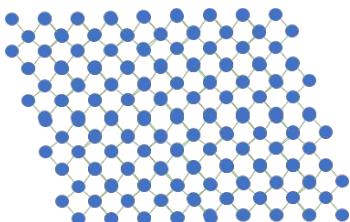
Spin Torque Transfer
(STT - RAM)



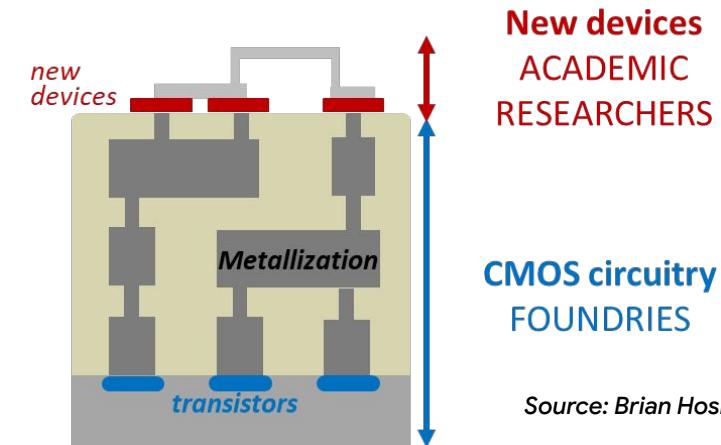
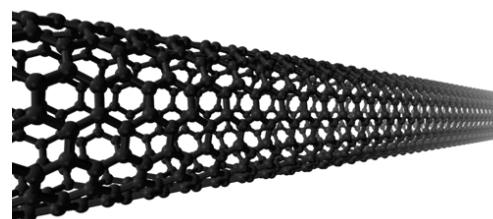
Conductive Bridge
(CB-RAM)



2D Materials



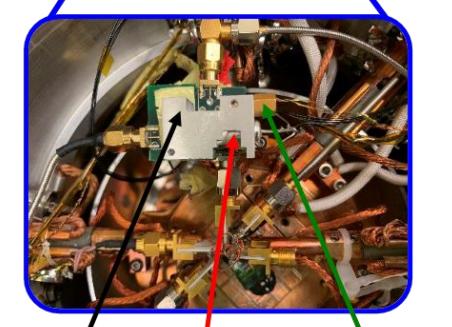
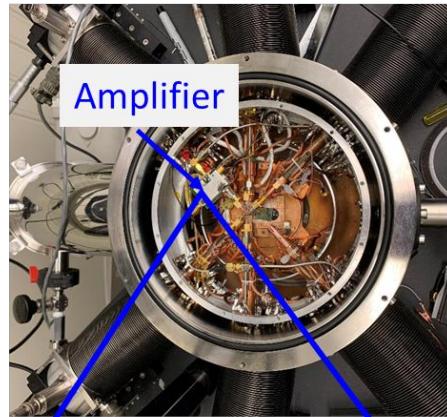
Nanotubes



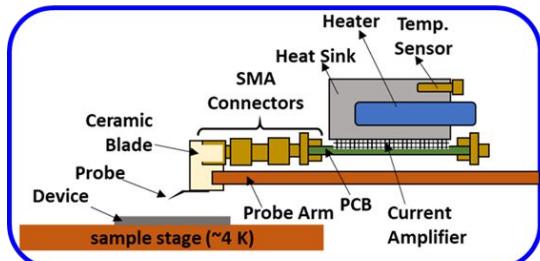
Source: Brian Hoskins, NIST

Reliable monolithic integration is a requirement for experimental prototyping

Open Cryogenic CMOS

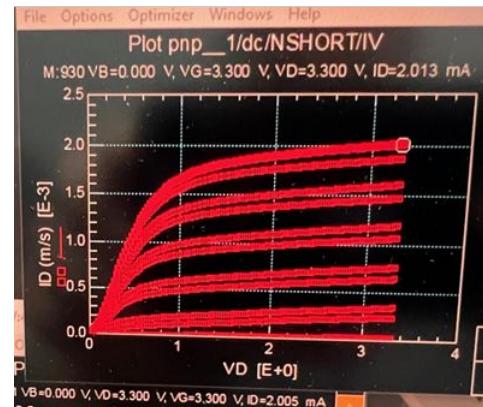


Time + Temperature
dependent
characterization

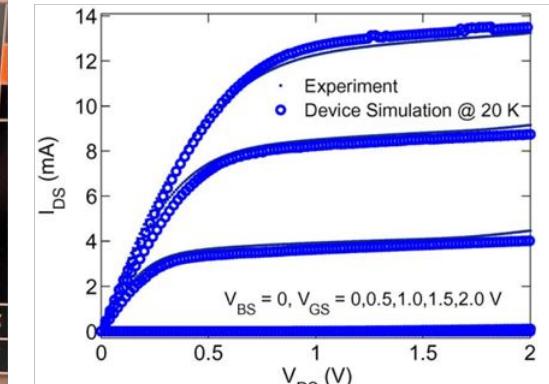


Cryogenic Models and Data of Open Sky130

Raw Data



Fit Models

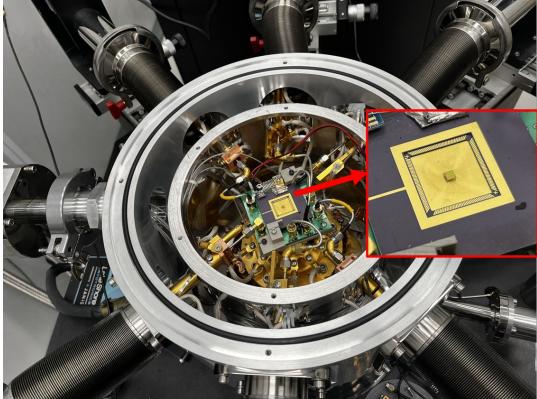


Google



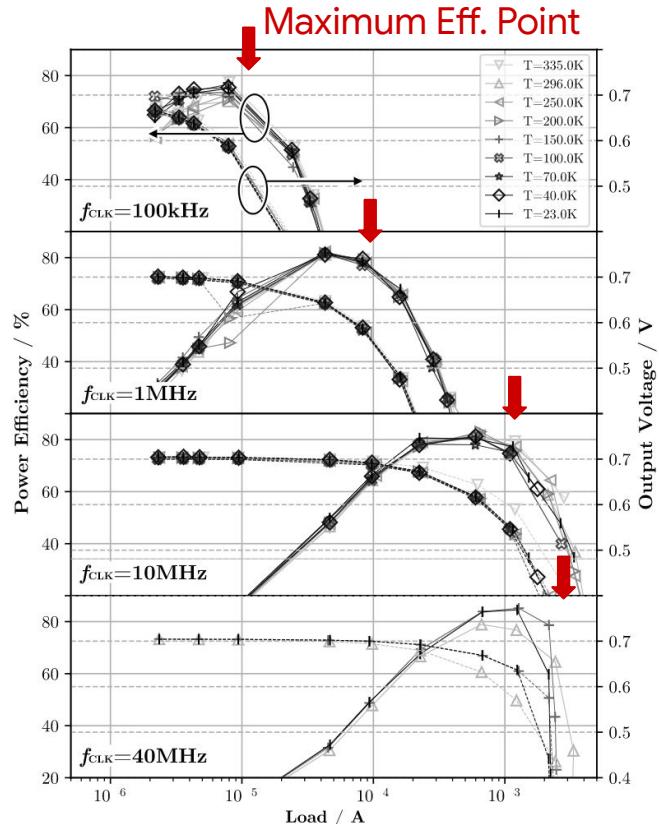
Automated PMU for Low-K Operation

Measurement Results



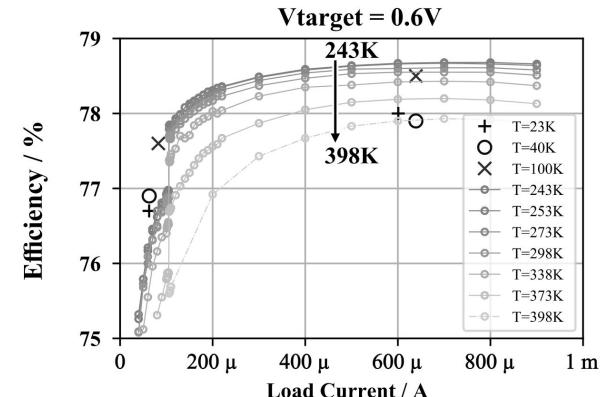
Cryogenic Test Setup

Experiments have shown constant behavior across a wide temperature range, down to cryogenic temperatures.

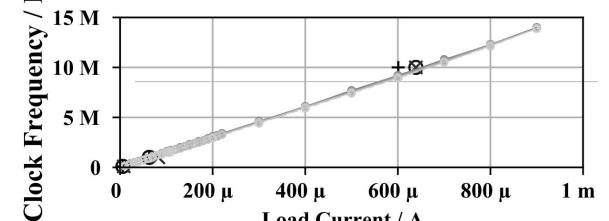


Power Efficiency & Output Voltage
Versus Load Current, Clock Freq., and Temperature

Robust against Temperature Variation



(a). Maximum Efficiency vs. Load Current

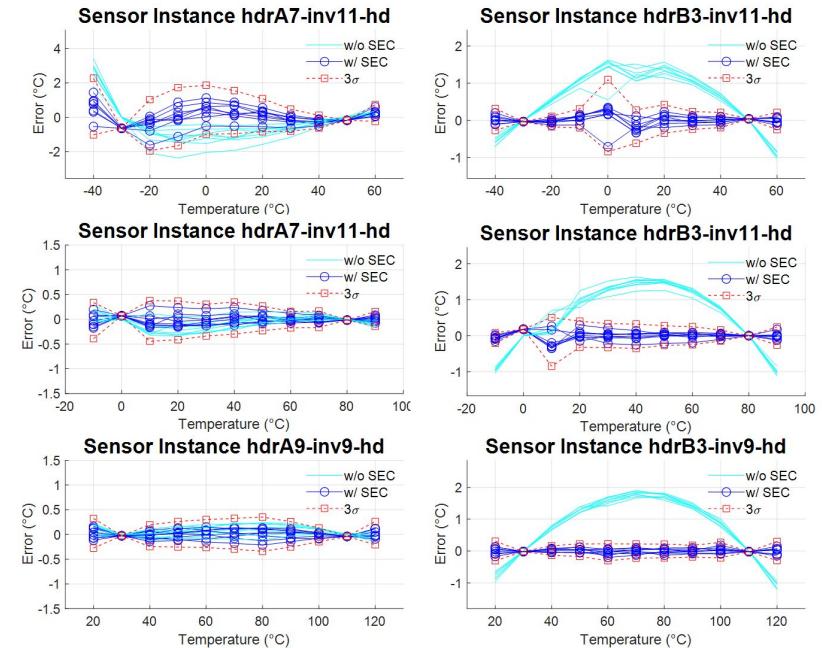
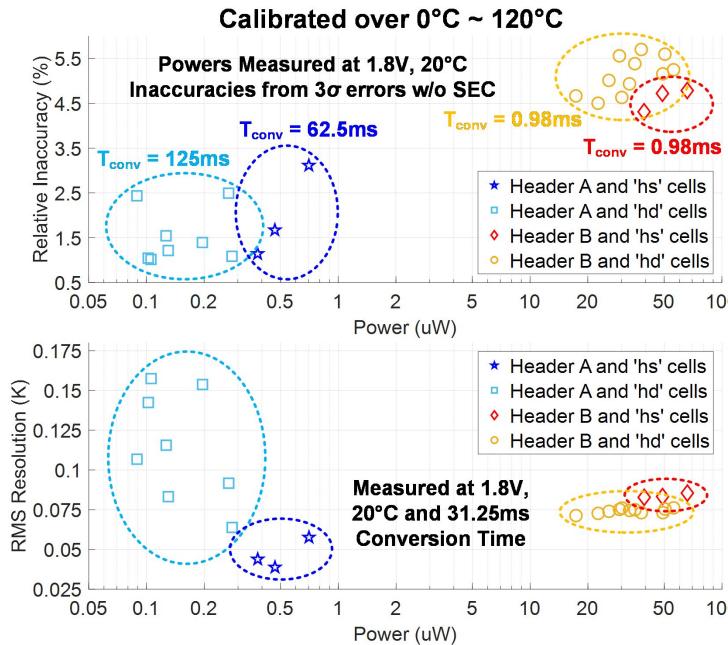
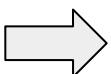
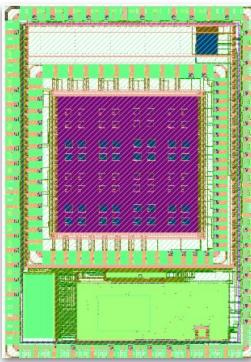


(b). Frequency vs. Load Current
at Maximum Efficiency Tracking

Emulated Closed-Loop Response
At Maximum-Power Tracking

Building Confidence in *Open* Design

Start of
Skywater's Open
MPW Program



MPW1

Dec Jun Aug Oct Dec Feb Apr Jun Aug Oct Dec Feb Apr Jun Dec Feb Apr Jun

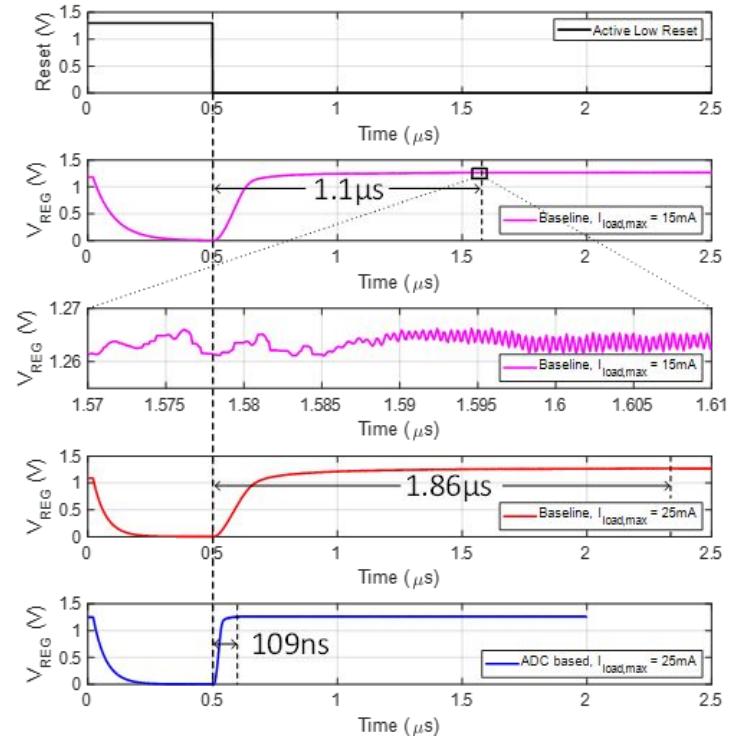
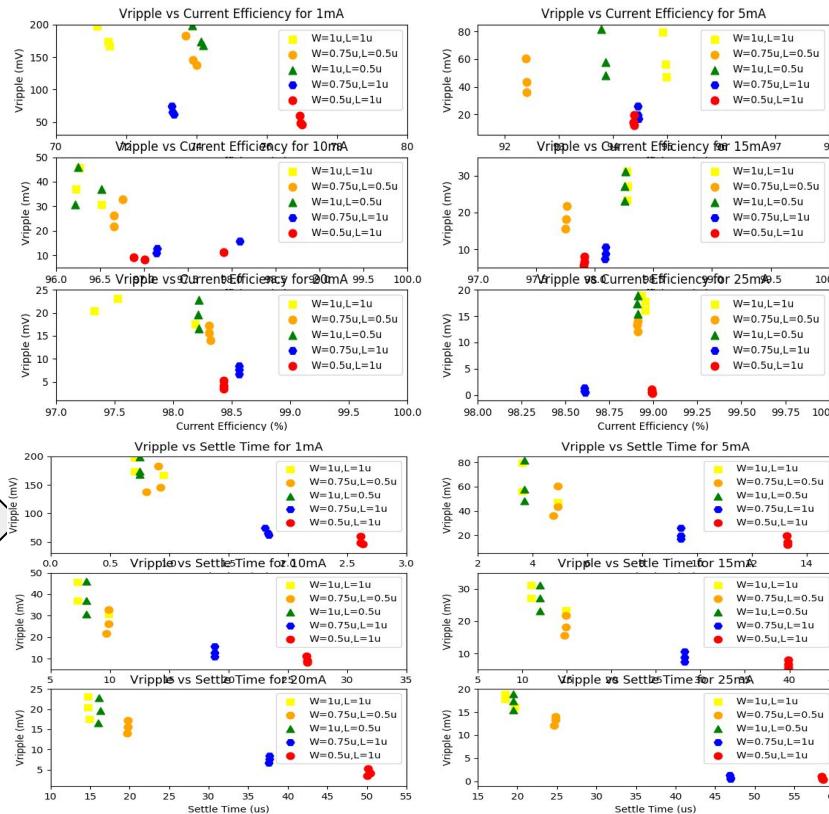
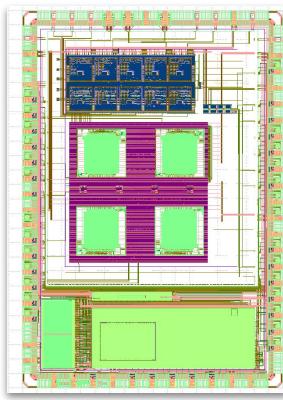
End of 2021
2020

2022

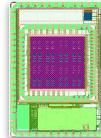
2024

Building Confidence in *Open* Design

Start of Skywater's Open MPW Program



SKY130



MPW1

MPW2

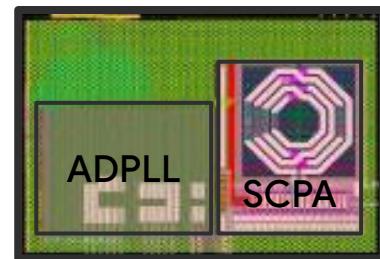
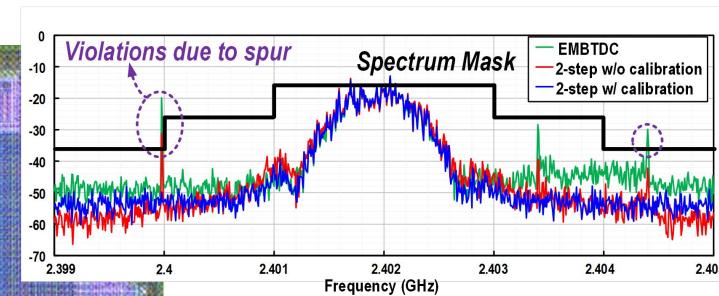
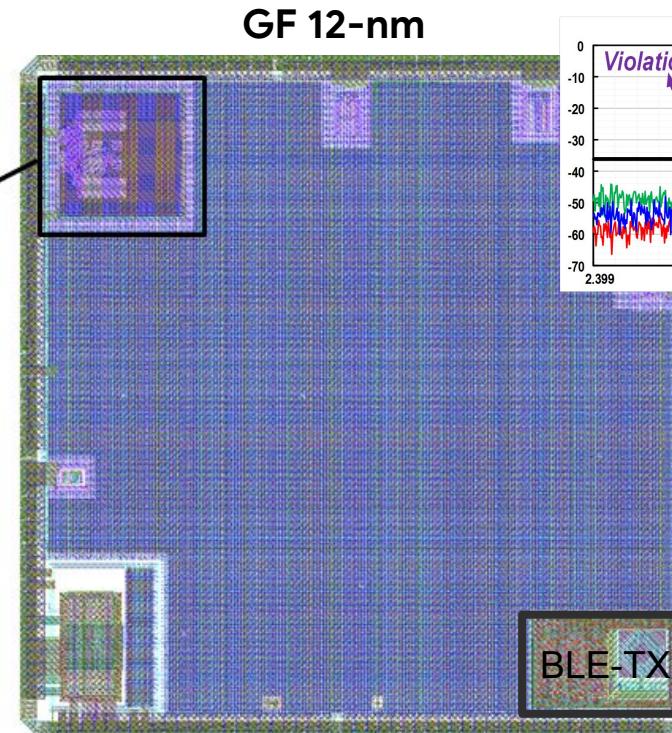
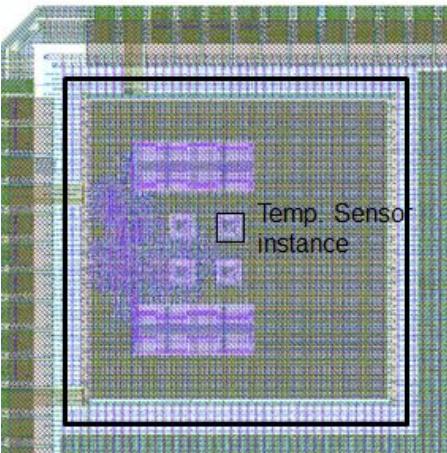
Dec Jun Aug Oct Dec Feb

2024

Building Confidence in *Open* Design

Tapeout through DARPA IDEA Program

- 1st tapeout in GF12LP using open source tools

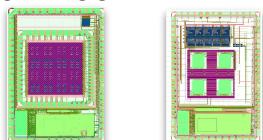


- Signoff using PT
 - @ TT|25C|0.8v|funcmax

350MHz

- Temperature sensors
 - T_{RANGE}: -20 to 100°C
 - Error: +/- 0.2°C (post-PEX)

SKY130



MPW1 MPW2 MPW3

Dec Jun Aug Oct

Dec Feb Apr Jun

Aug Oct Dec Feb Apr Jun

End of
2020 2021

2022

Feb
24th May
28th

2024

- ADPLL supports 1.8 to 2.7GHz

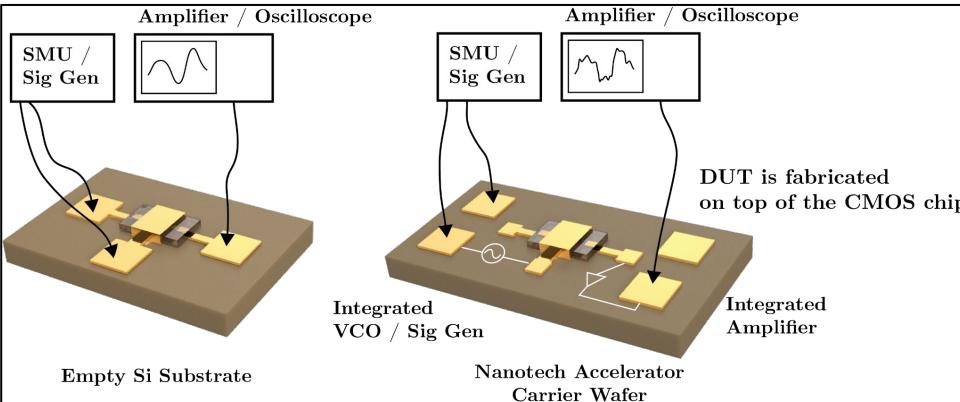
Building Confidence in *Open* Design

NIST

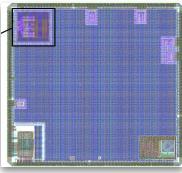
Nanofab. Accelerator
program w. NIST

Start of
Skywater's Open
MPW Program

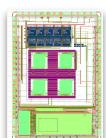
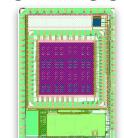
DARPA IDEA
Program



GF 12-nm



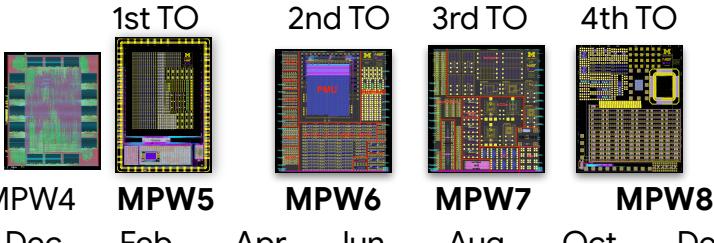
SKY130



MPW1 MPW2

Dec

End of
2020

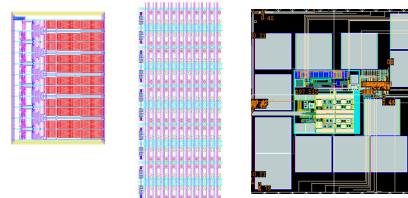


2022

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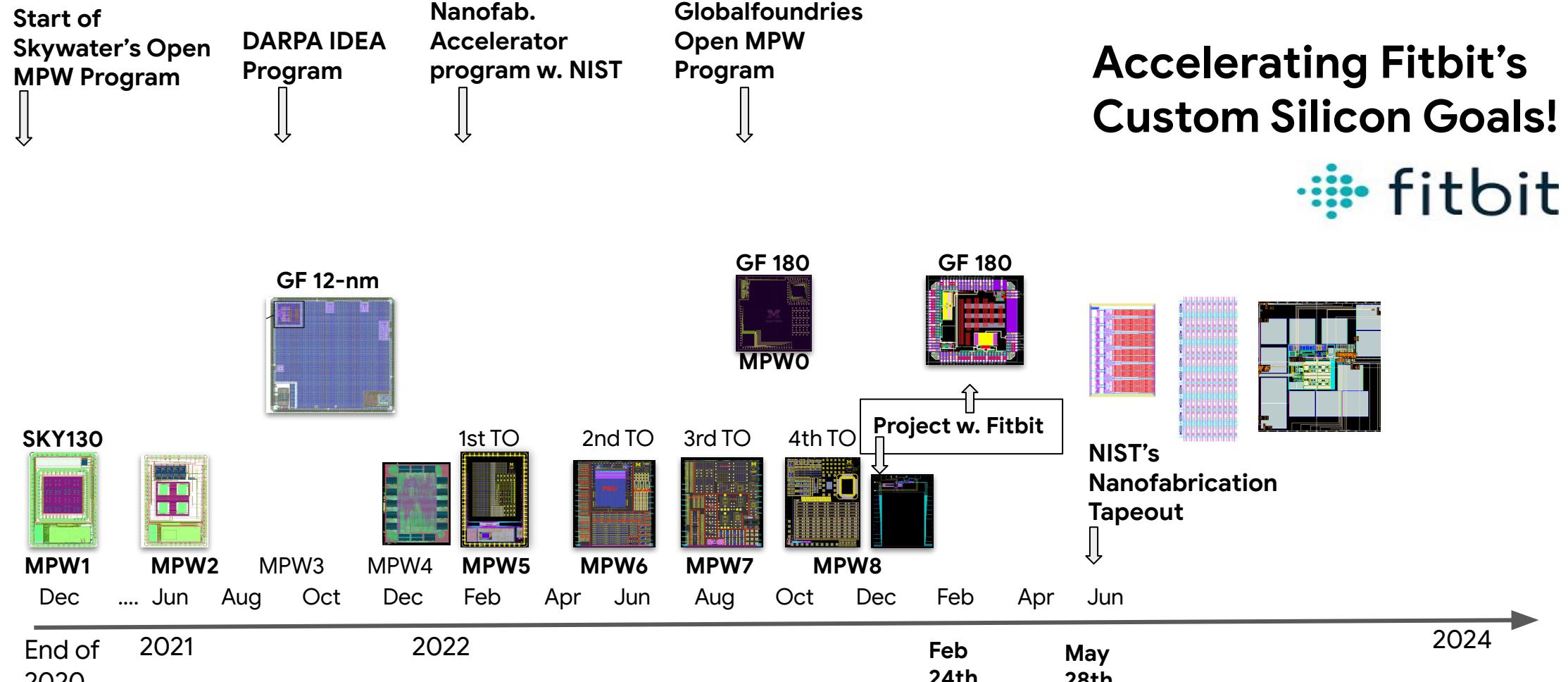
2024



NIST's
Nanofabrication
Tapeout



Building Confidence in *Open* Design



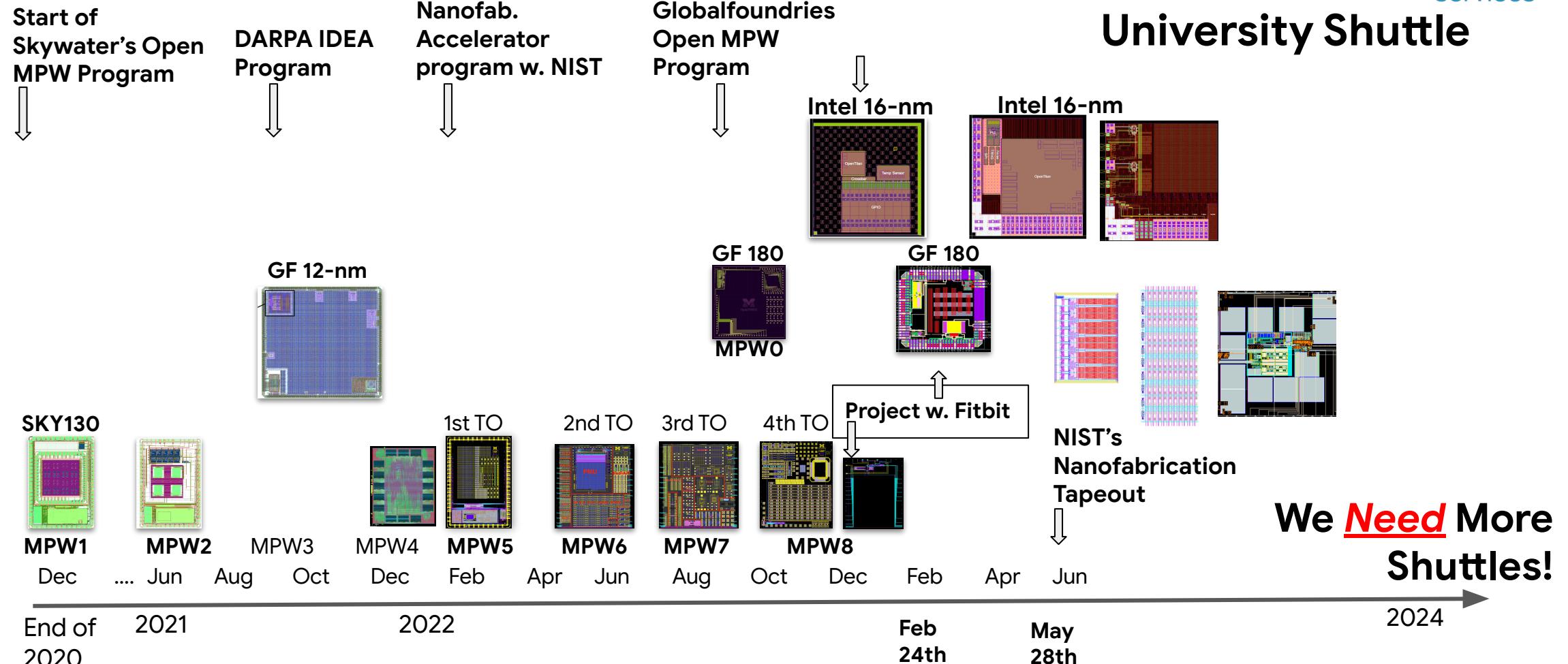
Accelerating Fitbit's Custom Silicon Goals!



Building Confidence in *Open* Design

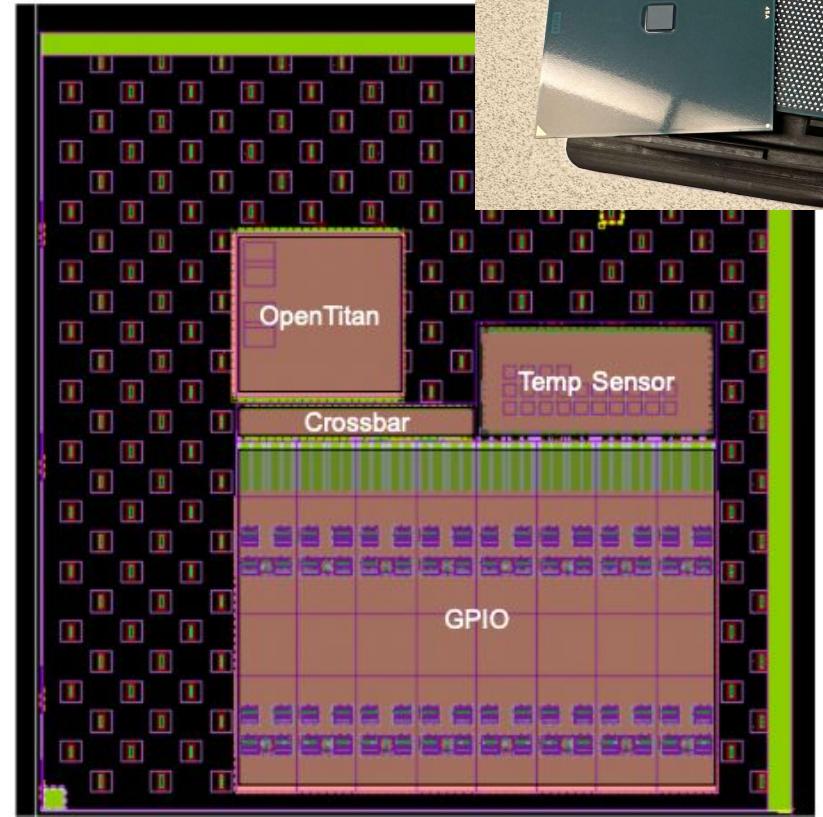
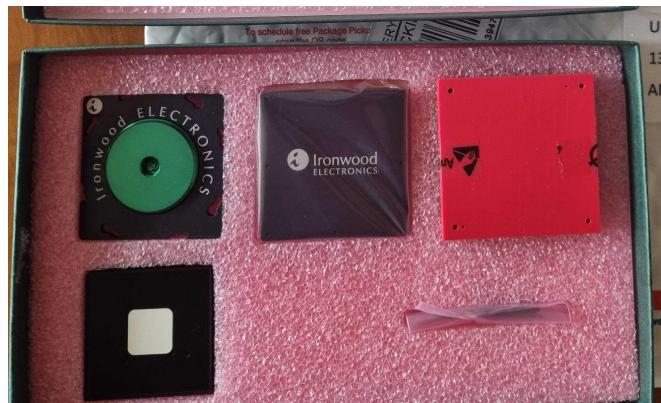
intel.
foundry
services

Intel's University Shuttle



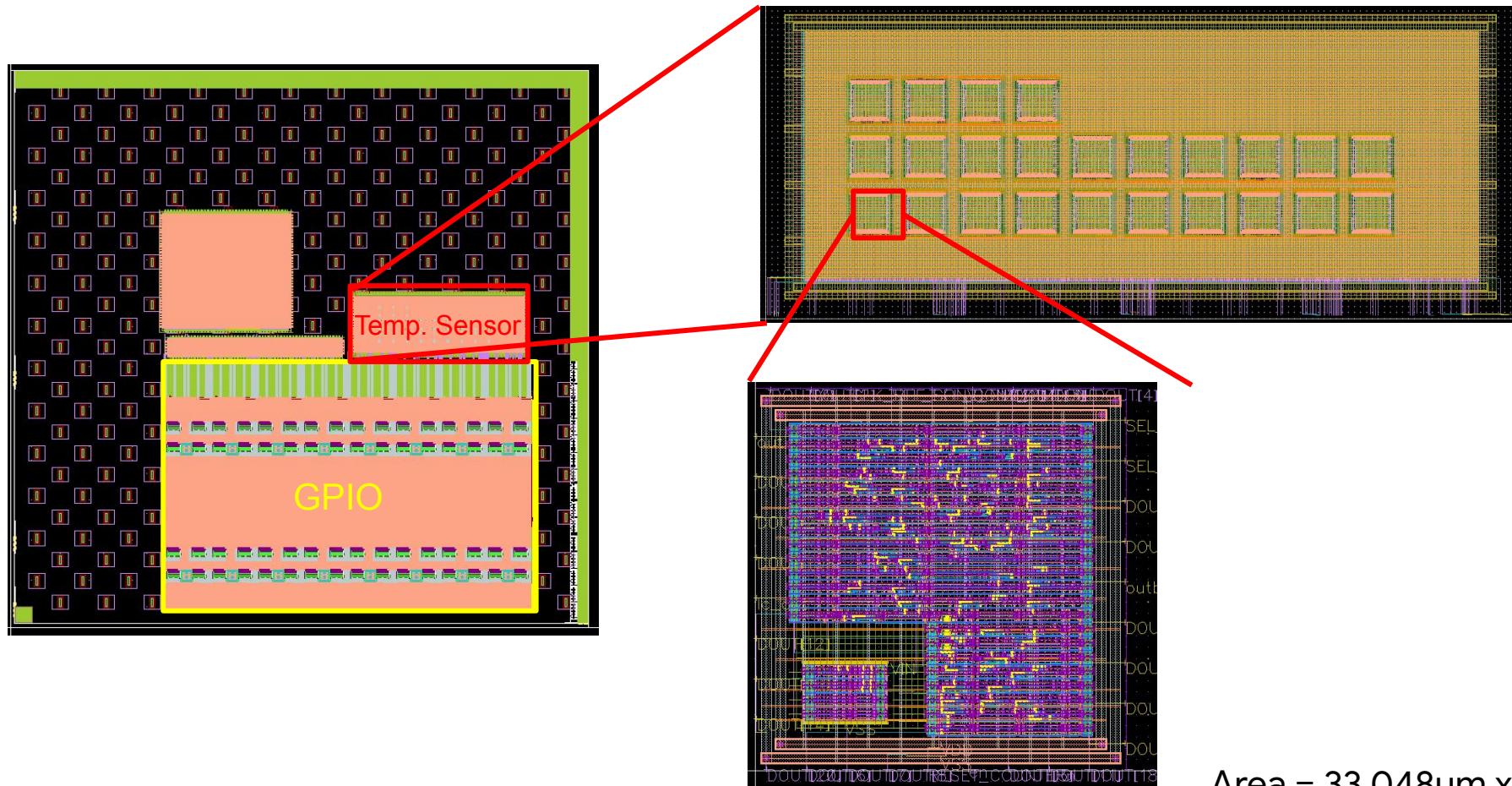
Tape Outs in Intel 16 - OpenTitan SoC

- Tapeout in Intel 16nm using OS tools
- PD and timing optimization using OpenROAD
- Used a modular flow to smoothly fill-in the gaps using proprietary tools
- Temperature Sensor RTL to GDS flow is fully Open-Source



Floorplan of Intel 16 tapeout Including OpenTitan, Temperature sensor array and crossbar using OpenROAD

24 Temperature Sensors Array

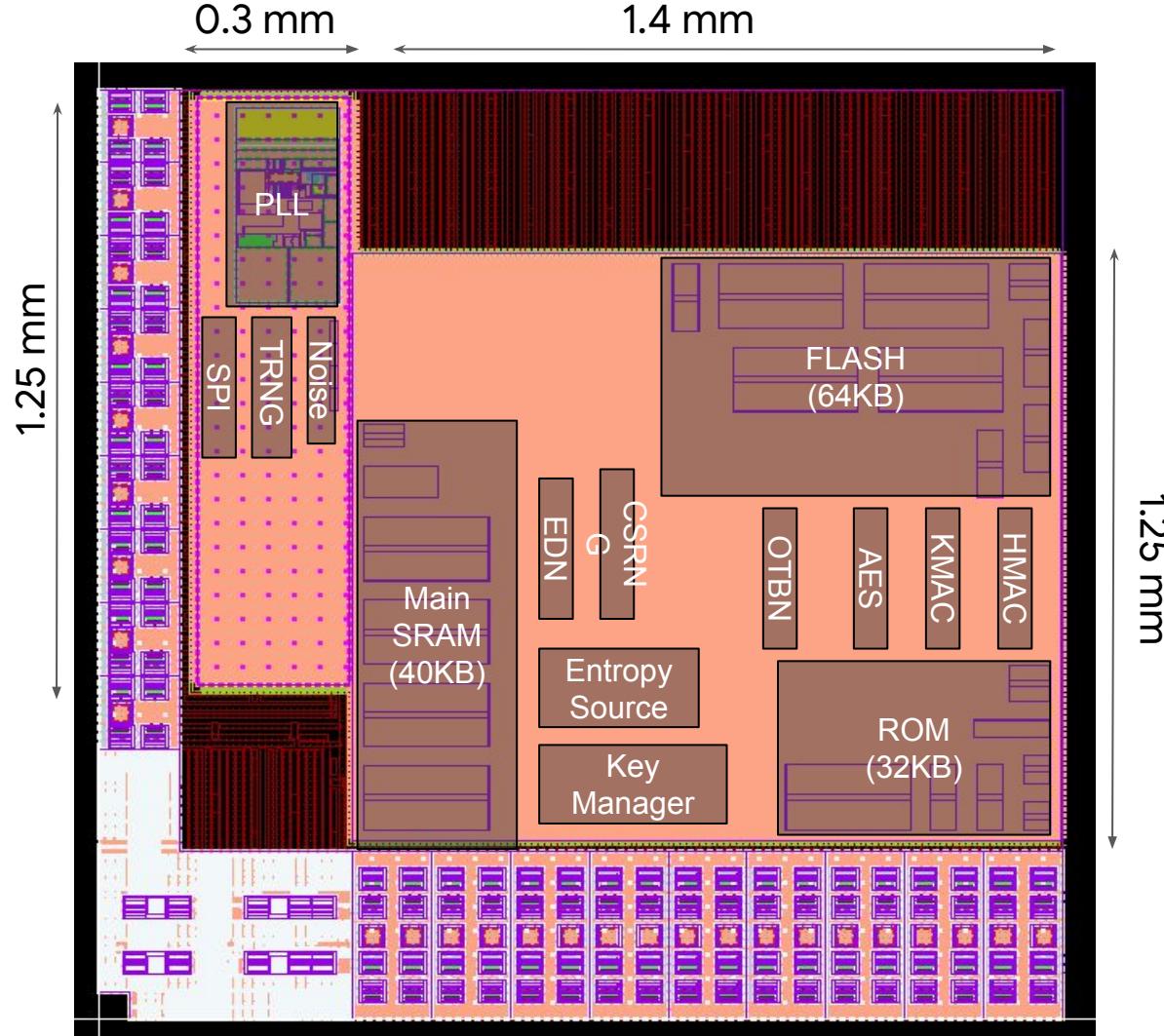


Area = 33.048um x 34.02um

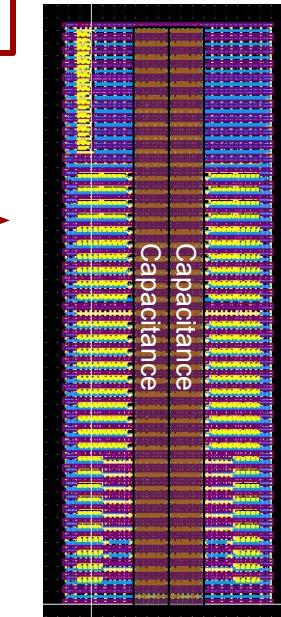
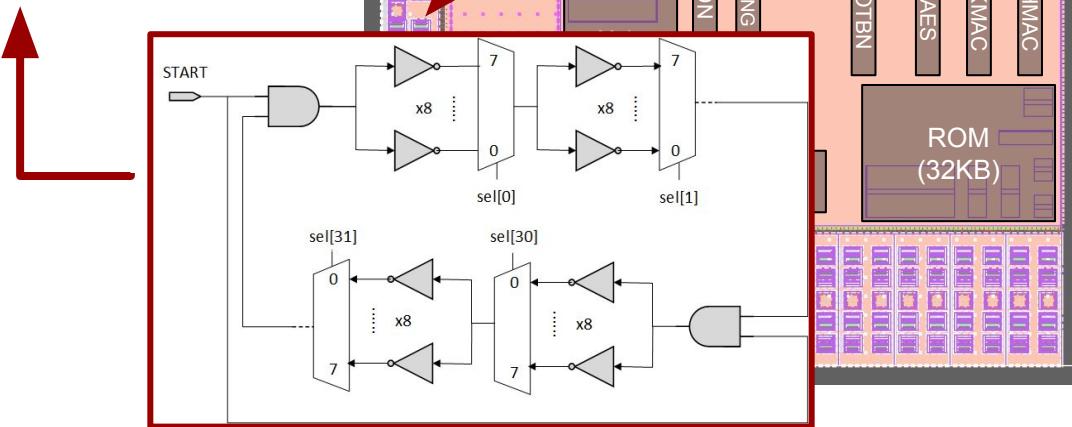
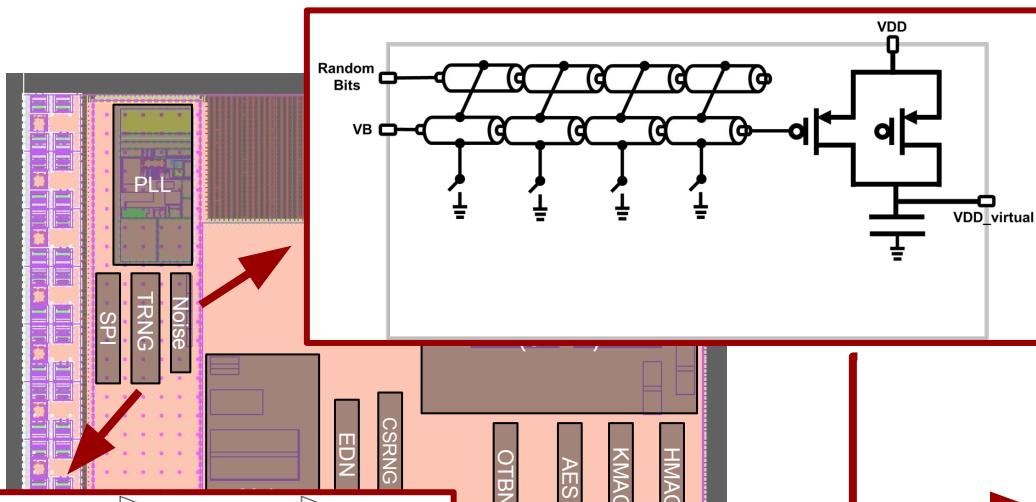
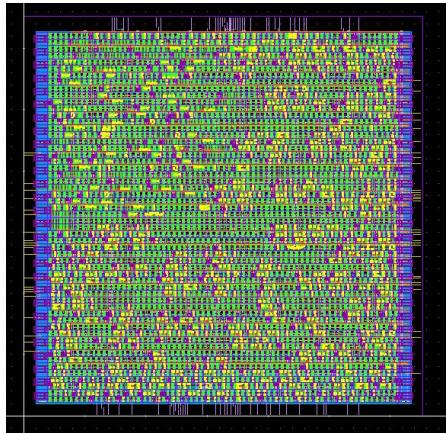
OpenTitan Root of Trust SoC - Final Version

- All digital edge tracing TRNG
- Tunable Noise Injection
- On-chip high speed PLL
- OpenTitan security subsystem
 - Crypto + Key Manager
 - Secure Memory

Frequency	28MHz
Memory Size	16KB
Gate Count	20K
# of Macros	26
Area	2.18mm ²



OpenTitan Root of Trust SoC - Final Version



What is next?

Bridging Gaps between **Hardware** & **Software**

Make custom silicon easier to
build, at scale, just like
software

```
$ gcc -OSilicon
```



“My god,
it’s full of **software!**”

Bridging Gaps between Hardware & Software

CONDA

Packaging

conda-eda

github.com/hdl/conda-eda

```
conda install --channel litex-hub \
    open_pdks.sky130a \
    openlane \
    xls
```



“My god,
it’s full of software!”



Reproducible, Reusable

Jupyter Notebook

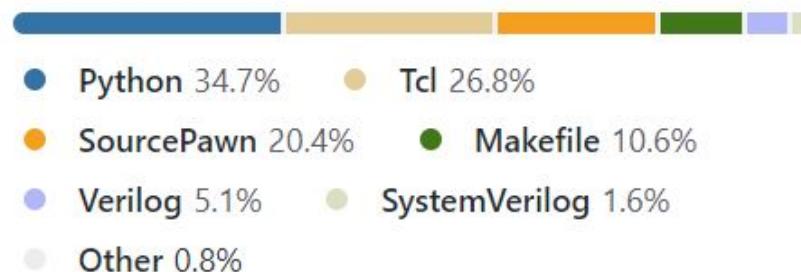
github.com/chipsalliance/silicon-notebooks/



Bridging Gaps between Hardware & Software

- OpenFASOC GitHub Repo is mainly Code and Documentation

Languages



"My god,
it's full of software!"

Bridging Gaps between Hardware & Software

- OpenFASOC GitHub Repo is mainly Code and Documentation
 - Auditable and Transparent
 - Regression Tests
 - Systematic Metrics Extraction
 - Dashboards



“My god,
it’s full of software!”

Bridging Gaps between Hardware & Software

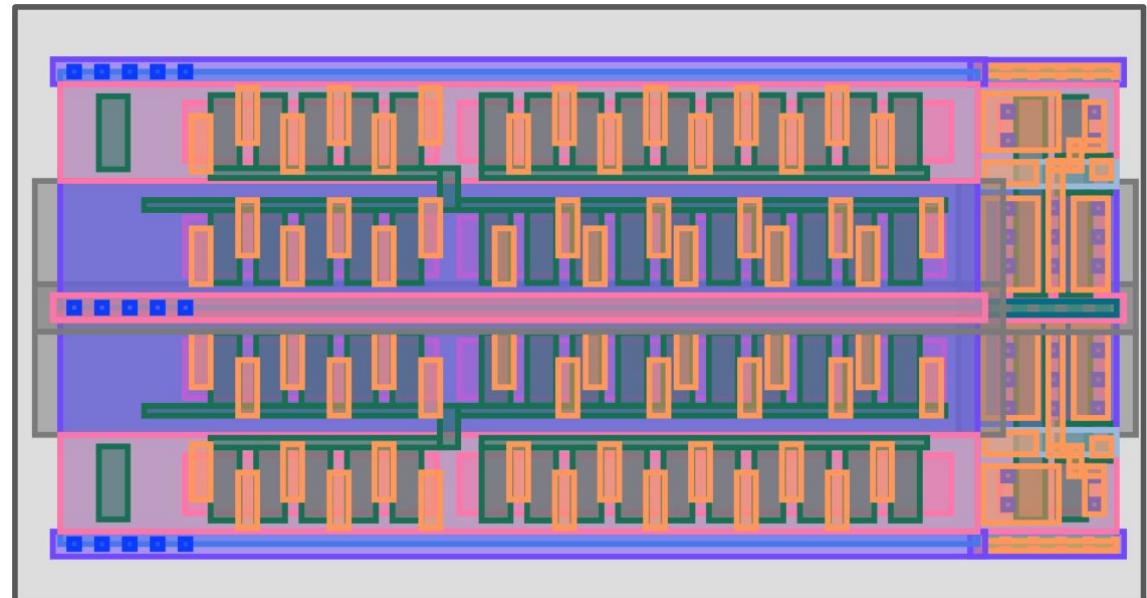
- OpenFASOC GitHub Repo is mainly Code and Documentation
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 - Regression Tests
 - Systematic Metrics Extraction
 - Dashboards
- Analog Automation requires collaborative Work
 - EDA, Analog/RF/Circuits, Software



“My god,
it’s full of software!”

Generator with a Higher Control/Precision

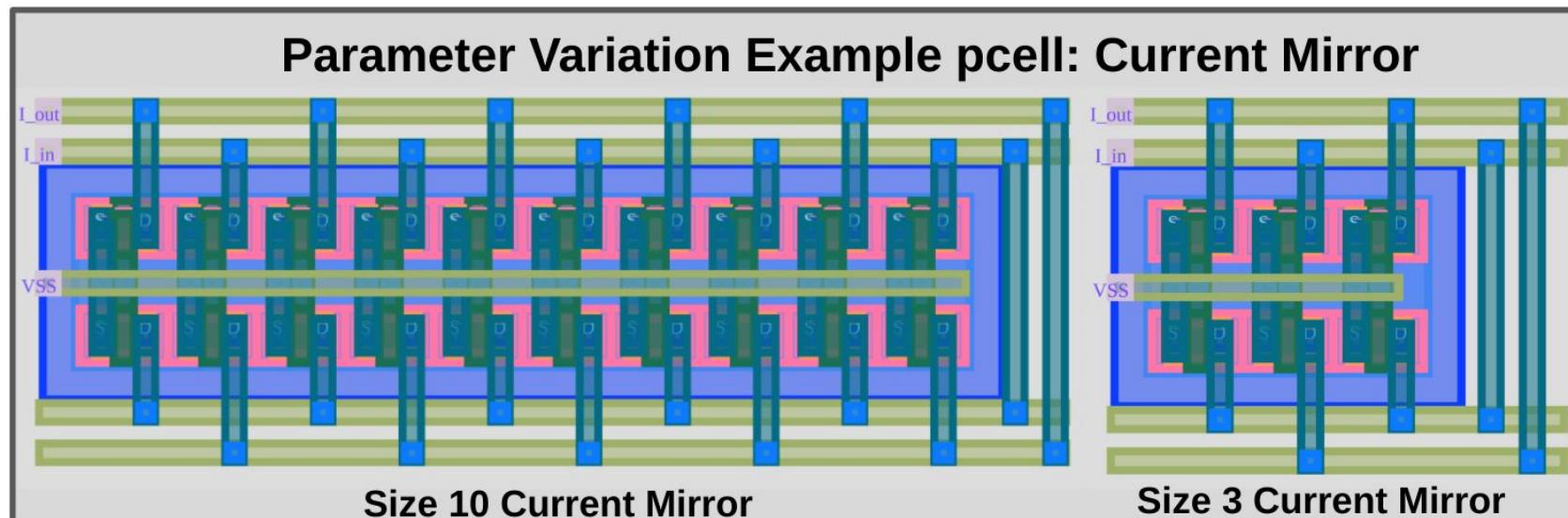
- Addresses porting Aux-cells to new PDK
- Programmatic layout provide fine control with automation



Auto-Generated Comparator Cell

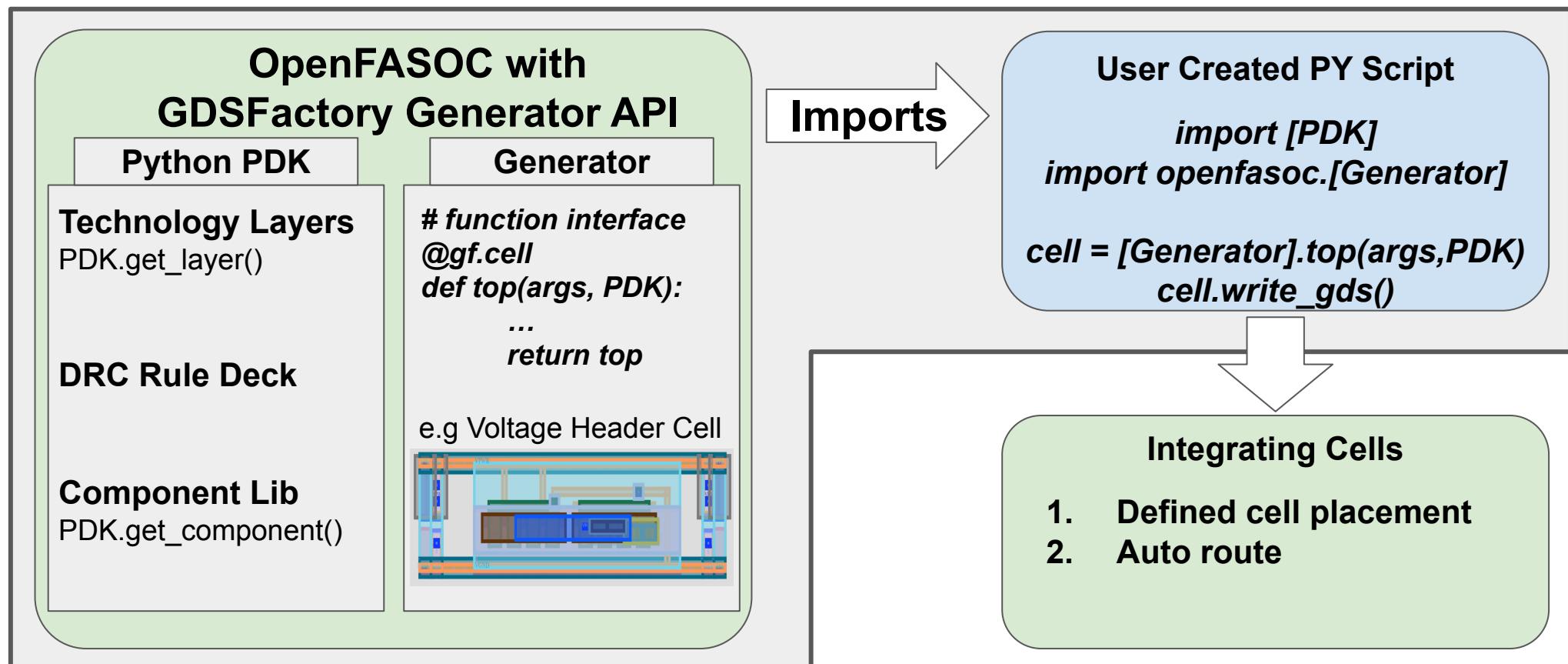
Generator with a Higher Control/Precision

- Object oriented code provides flexibility
- PDK -> py class
- Generators -> py function
- User codes hardware by importing py packages



Parameter Variation

Integration with GDSfactory & OpenROAD



Reproducible, Reusable Results using Notebooks & **Open** PDKs

- Selected by the US Consulate in Japan to organize workshops and training for the Japanese Workforce in Kyushu Area



**U.S. EMBASSY & CONSULATES
IN JAPAN**

U.S. DEPARTMENT OF STATE

U.S. Consulate Fukuoka

Notice of Funding Opportunity

Funding Opportunity Title: FY2023 U.S. Consulate Fukuoka: High-Tech Labor Force Curriculum Development Workshop

Funding Opportunity Number: FUKUOKA-PAS-FY23-02

Deadline for Applications: February 19, 2023 (by 11:59 pm JST)

Assistance Listing Number: 19.040 – Public Diplomacy Programs

Reproducible, Reusable Results using Notebooks & **Open** PDKs

- **Selected** by the US Consulate in Japan to organize **workshops** and **training** for the Japanese **Workforce** in Kyushu Area
 - Partnering with local Universities



**U.S. EMBASSY & CONSULATES
IN JAPAN**

U.S. DEPARTMENT OF STATE

U.S. Consulate Fukuoka

Notice of Funding Opportunity

May 1, 2023, 3:05 AM



FY23 U.S. Consulate Fukuoka: High-Tech Labor Force
Curriculum Development Workshop

FUKUOKA-PAS-FY23-02

May 19, 2023 (by 11:59 pm JST)

- Public Diplomacy Programs

Tokyo, PASGrants <TokyoPASGrants@state.gov>

to Strader, Masayuki, Tracy, Caitlin, me, Michelle ▾

Dear Tracy Schwab,

Your application submitted on February 18, 2023 in response to the U.S. Consulate Fukuoka's Notice of Funding Opportunity FUKUOKA-PAS-FY23-02, has been selected for funding.

The Grants Officer and the Grants Officer Representative for your proposed project are as follows:

Grants Officer: Strader Payton

Grants Officer Representative: Masayuki Miyauchi

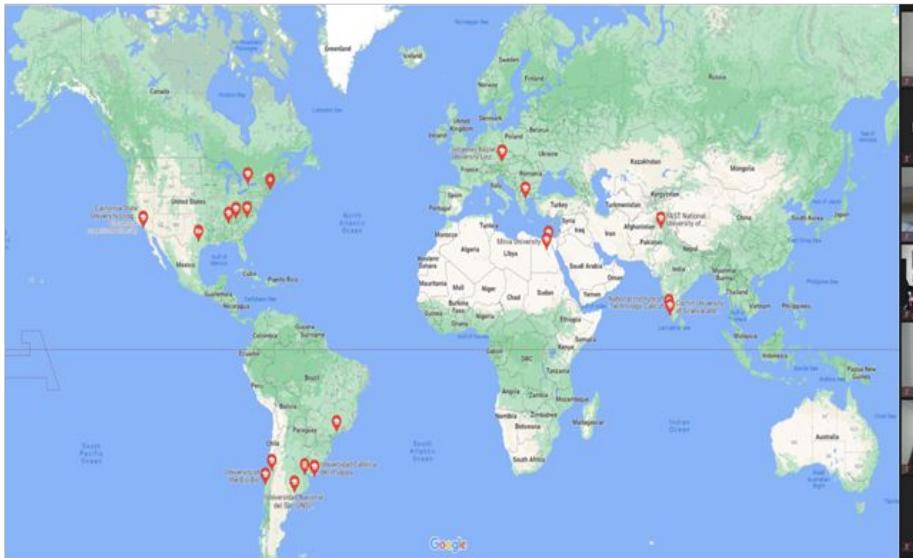
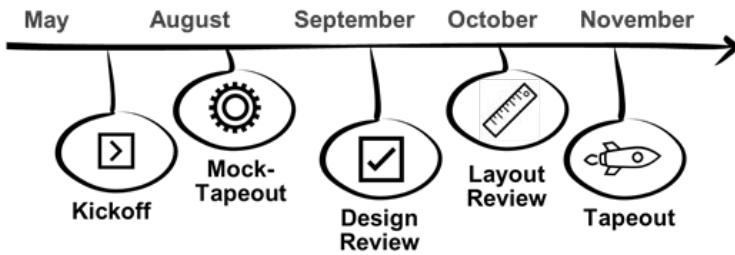
IEEE SSCS TC OSE

Activities

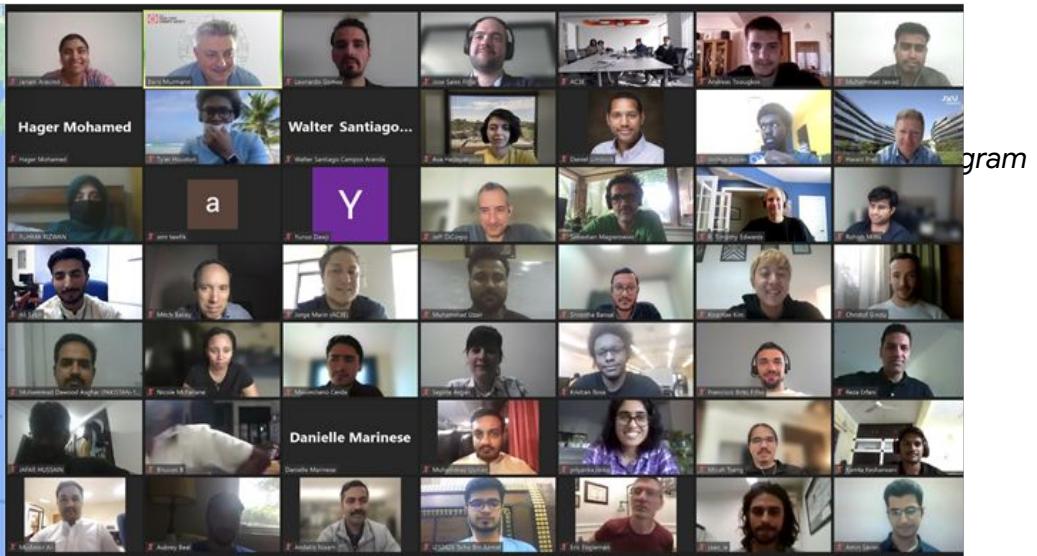


SSCS PICO Chipathon

- 2021: 61 submissions, 18 selected (11 taped out)
- 2022: 54 submissions, 22 selected (14 taped out)



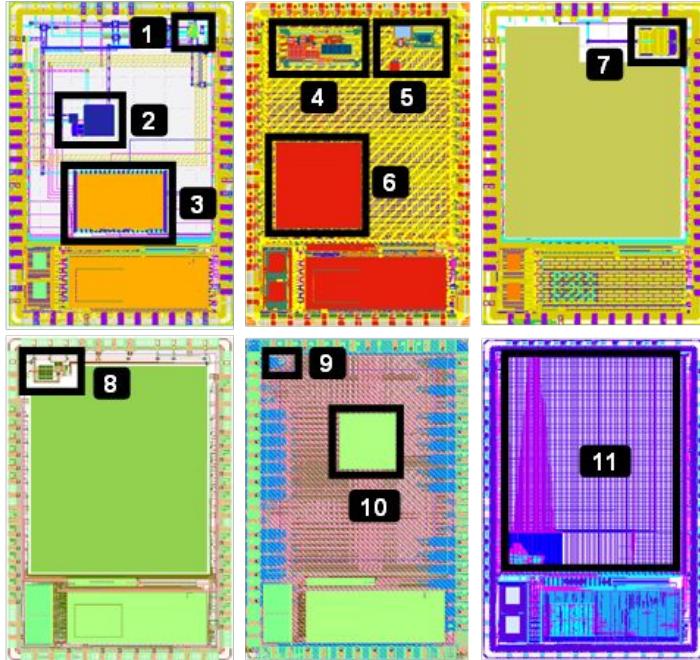
2022 selected teams from 10 countries, 5 continents



June 22, 2022, kick-off meetup with over 100 attendees



2021 Chipathon

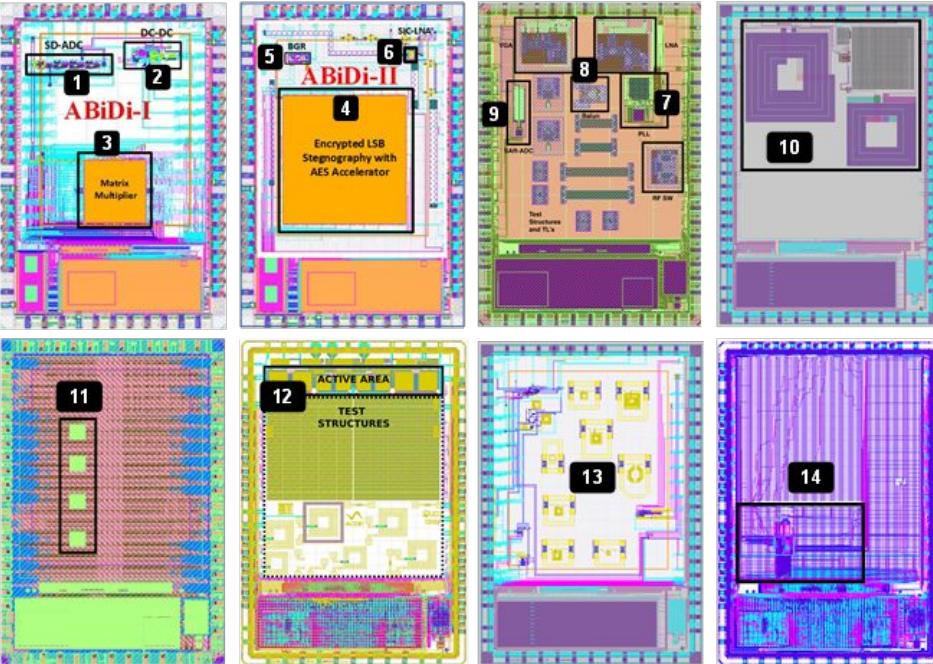


	Function	Team	Chip URL
1	5G bidirectional amplifier	Pakistan3 (FAST National University)	https://efabless.com/projects/560
2	Wireless power transfer unit	Pakistan2 (FAST National University)	
3	Variable precision fused multiply-add unit	Pakistan1 (FAST National University)	
4	Oscillator-based LVDT readout	India2 (Anna University)	
5	Temperature sensor	India1 (Anna University)	https://efabless.com/projects/474
6	GPS baseband engine	India3 (Anna University)	
7	Ultra-low-power analog front-end for bio signals	Brazil2 (U. Federal de Santa Catarina)	https://efabless.com/projects/476
8	TIA for quantum photonics interface	USA4 (University of Virginia)	https://efabless.com/projects/470
9	Bandgap reference	Egypt (Cairo University)	
10	Neural network for sleep apnea detection	USA2 (University of Missouri)	https://efabless.com/projects/473
11	SONAR processing unit	Chile (University of the Bio-Bio)	https://efabless.com/projects/540

- Paid runs via Efabless chipIgnite (130 nm SkyWater)
- All designs are open source

Magazine article: "SSCS PICO Contestants Cross the Finish Line," <https://ieeexplore.ieee.org/document/9694491>

2022 Chipathon

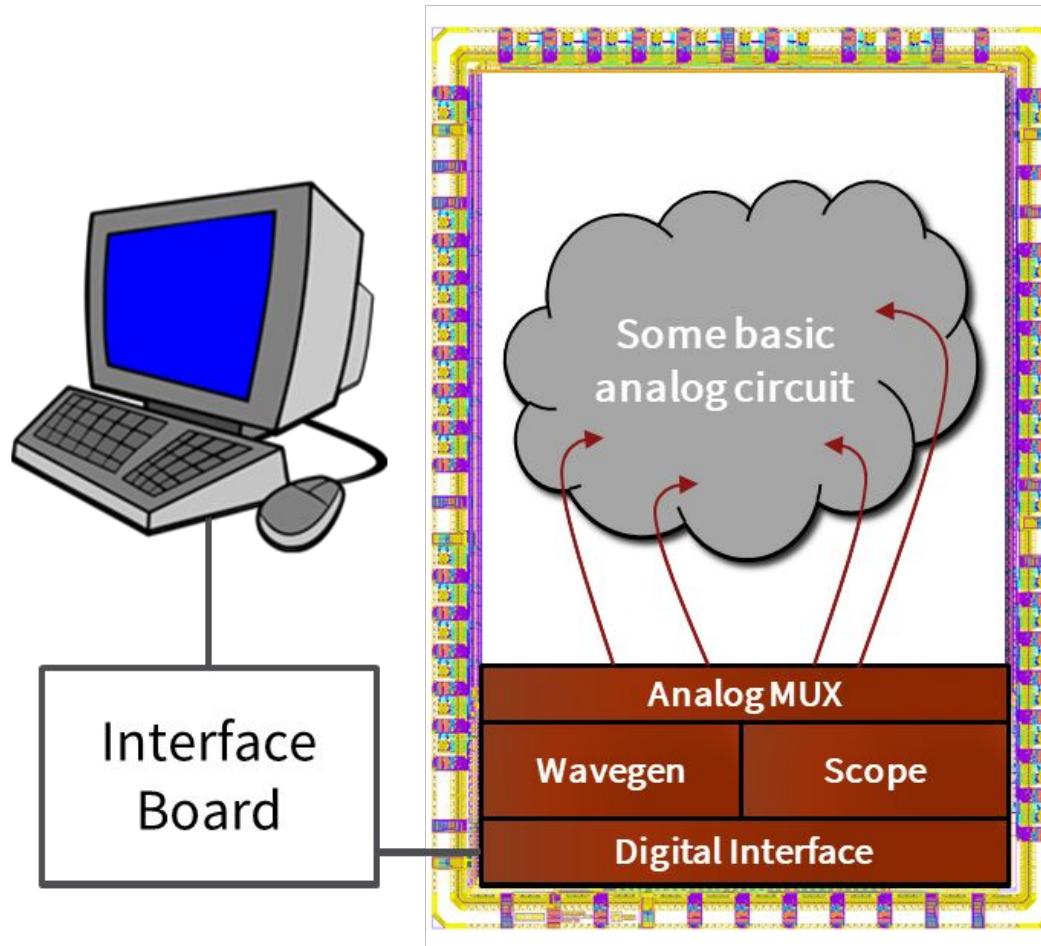


	Function	Team	Chip URL
1	Spatial Sigma-Delta ADC	Pakistan1 (FAST National University)	https://platform.efabless.com/projects/1486
2	On-Chip DCDC Converter with Fast Transient Response	Pakistan4 (FAST National University)	
3	Matrix Multiplier for AI at the Edge	Pakistan7 (FAST National University)	
4	Encrypted LSB Steganography with AES Accelerator	Pakistan2 (FAST National University)	
5	CMOS Bandgap Reference	Pakistan3 (FAST National University)	
6	Self-Interference Cancellation LNA	Pakistan4 (FAST National University)	
7	Sub-Sampling PLL for SerDes Applications	Austria (Johannes Kepler Univ., Linz)	
8	60 GHz Demonstrator Chip	Brazil (University of São Paulo)	
9	Low-Power 10-bit SAR ADC	USA1 (University of Alabama & MIT Lincoln Lab)	
10	Boost Converter for Battery-Powered IoT Applications	Greece (Aristotle University of Thessaloniki)	https://platform.efabless.com/projects/1457
11	Radiation-Hardened ALU	USA2 (North Carolina A&T State University)	https://platform.efabless.com/projects/1593
12	DC-DC Buck Converter for CubeSat	Chile ¹ /Argentina ² /Uruguay ³ ¹ Universidad Técnica Fed. Santa María ² Universidad Nacional del Sur & Instituto Nacional de Tecnología Industrial ³ Universidad Católica	https://platform.efabless.com/projects/1427
13	Electrochemical Water Quality Monitoring	USA5 (University of Tennessee)	https://platform.efabless.com/projects/1469
14	Mix-Pix - A Mixed-Signal Circuit for Smart Imaging	Chile (Universidad del Bío-Bío)	https://platform.efabless.com/projects/1494

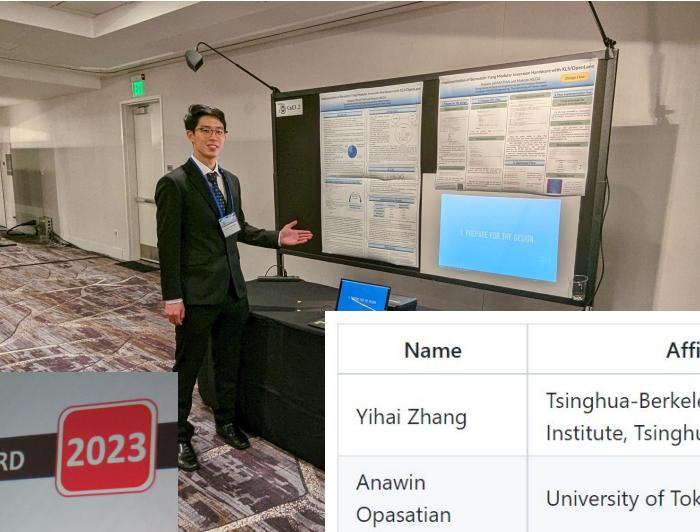
Magazine article: "Meet the SSCS PICO Chipathletes," <https://ieeexplore.ieee.org/document/9950763>

2023 Chipathon (Ongoing)

- Build on-chip waveform generator and “oscilloscope” macros
 - Collection of generally useful IP blocks
- Enable testing of low frequency analog circuits using only a PC
- Tape out first prototypes and improve with community over time



Notebook Code a Chip Competition at ISSCC'23



Name	Affiliation	Notebook Title
Yihai Zhang	Tsinghua-Berkeley Shenzhen Institute, Tsinghua University China	GreenRio 2: A Linux-compatible RISC-V Processor Developed with A Fully Open-Source EDA Flow
Anawin Opasatian	University of Tokyo (Japan)	Bernstein-Yang Modular Inversion with XLS/OpenLane
Mauricio Montañares	University of Concepción (Chile)	Sonar On Chip Project
Nealson Li	Georgia Institute of Technology (USA)	Coordinate Rotation Digital Computer (CORDIC) with OpenLane
HyungJoo Park	Hanyang University (South Korea)	Scan Register layout generation using laygo2
Ali Hammoud	University of Michigan (USA)	OpenFASoC: Digital LDO Generator
Nimish Shah	KU Leuven (Belgium)	DPU: DAG Processing Unit for probabilistic ML and sparse matrix algebra



Notebook Code a Chip Competition at VLSI'23

Example: Winner of VLSI 2023 Code-a-Chip Contest

 Open in Colab

Design and Optimization of Analog LDO with Relational Graph Neural Network and Reinforcement Learning

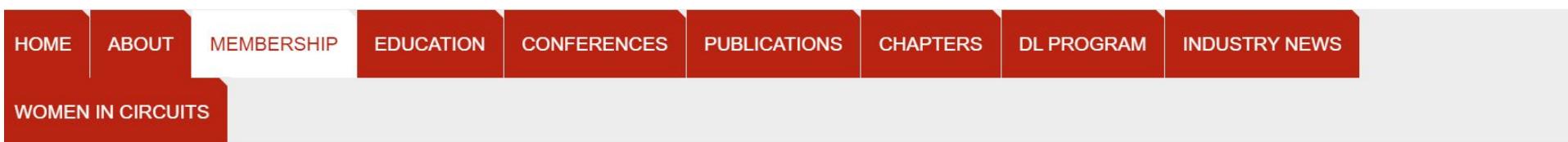
Zonghao Li Team, March 2023
SPDX-License-Identifier: Apache-2.0

Name	Affiliation	IEEE Member	SSCS Member
Zonghao Li (Lead) Email ID: zonghao.li@isl.utoronto.ca	University of Toronto	Yes	Yes
Anthony Chan Carusone (Advisor) Email ID: tony.chan.carusone@isl.utoronto.ca	University of Toronto	Yes	Yes

https://github.com/sscs-ose/sscs-ose-code-a-chip.github.io/blob/main/VLSI23/accepted_notebooks/ldo_rgcn_rl/ldo_rgcn_rl.ipynb

“Code-a-Chip” Notebook Competition at VLSI'23 - Kyoto

- IEEE Solid-State Circuits Society (SSCS) Open-Source Ecosystem (OSE)
 - <https://github.com/sscs-ose/sscs-ose-code-a-chip.github.io>



/ Home / Membership / Awards / IEEE SSCS “Code-a-Chip” Travel Grant Awards

IEEE SSCS “Code-a-Chip” Travel Grant Awards

IEEE SSCS “Code-a-Chip” Travel Grant Awards at the 2023 Symposium on VLSI Technology and Circuits

The IEEE SSCS Code-a-Chip Travel Award was created to:

1. Promote reproducible chip design using open-source tools and notebook-driven design flows and
2. Enable up-and-coming talents as well as seasoned open-source enthusiasts to travel to IEEE SSCS conferences and interact with the leading-edge chip design community.

Monday AM Session @ ISCAS 2023

11:30 – 13:00

Review of the First Silicon Results in the Open Source Ecosystem

Room: San Carlos III (Marriott)

Session Chair(s): Mehdi Saligane, *University of Michigan*
Priyanka Raina, *Stanford University*

11:30

2273: An Open Source Compatible Framework to Fully Autonomous Digital LDO Generation

Yaswanth Kumar Cherivirala, Mehdi Saligane, David Wentzloff
University of Michigan, Ann Arbor, United States

11:48

2290: Design of Cryo-CMOS Analog Circuits Using the Gm/ID Approach

Christian Enz, Hung-Chi Han
École Polytechnique Fédérale de Lausanne, Switzerland

12:06

2314: SRAM Design with OpenRAM in SkyWater 130nm

Jesse Cirimelli-Low^{2}, Muhammed Hadir Khan^{2}, Samuel Crow^{2}, Amogh Lonkar^{2},
Bugra Onal^{2}, Andrew Zonenberg^{1}, Matthew Guthaus^{2}
^{1}IO Active, United States; ^{2}University of California, Santa Cruz, United States

11:24

2326: An Open-Source 4x8 Coarse-Grained Reconfigurable Array Using SkyWater 130 nm Technology and Agile Hardware Design Flow

Po-Han Chen, Charles Tsao, Priyanka Raina
Stanford University, United States

12:42

2327: Open-Source, End-to-End Auditable Tapeout of Hardware Cryptography Module

Anish Singhani
Carnegie Mellon University, United States

180 Attendees!! Record attendance among all workshops at VLSI Symposium

Open Source PDKs and EDAs, Community Experiences toward Democratization of Chip Design

Organizer : Makoto Ikeda (The University of Tokyo)

Organizer : Mehdi Saligane (University of Michigan)

Since its launch in 2020, the Open MPW shuttle program has received over 500 submissions from around the world. This workshop aims to share the latest developments in open source PDKs and EDAs, as well as to discuss the challenges and opportunities for democratizing chip design. The workshop will feature presentations from leading experts in the field, including measured results, foundry perspectives, and discussions on the future of open source chip design.

About Makoto Ikeda

Makoto Ikeda received his BE, ME, and Ph.D. degrees all in EE department of the University of Tokyo. He is currently a professor at d.lab, the University of Tokyo. This workshop is co-organized with Dr. Mehdi Saligane from the University of Michigan.

| 1. Design experience: “The Journey of Two Novice LSI Enthusiasts: Towards Open MPW”, Toshiaki Kondo, Department of Electrical and Computer Engineering, University of Communications and Yuki Azuma, University of Tsukuba

| 2. From Zero to 1000 Open Source Custom Designs in Two Years, Mehdi Saligane, Michigan Institute for Circuits and Electronics (MICL), University of Michigan

| 3. The SKY130 Open Source PDK: Building an Open Source Innovation Ecosystem, Michael J. Fischer, University of Michigan

| 4. Open Source Chip Design on GF180MCU – A foundry perspective, Karthik Chandrasekaran, Global Foundries



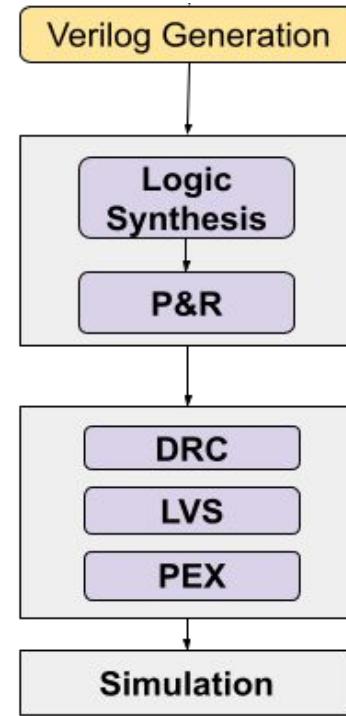
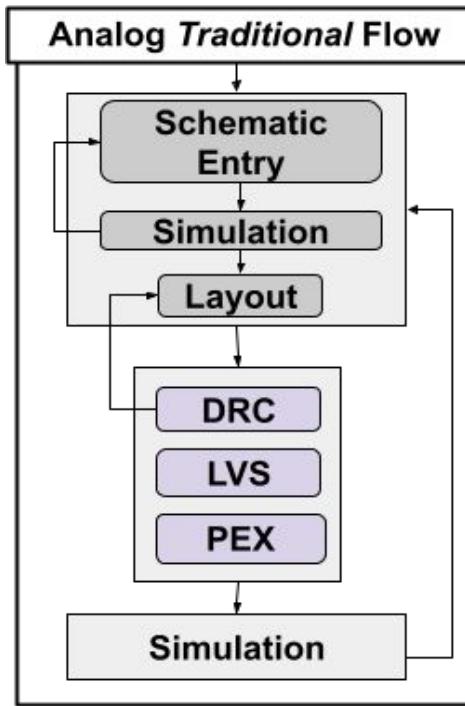
The End!

Traditional vs Automated Analog Design

Analog vs. Digital design flow



Automated
Manual/Custom

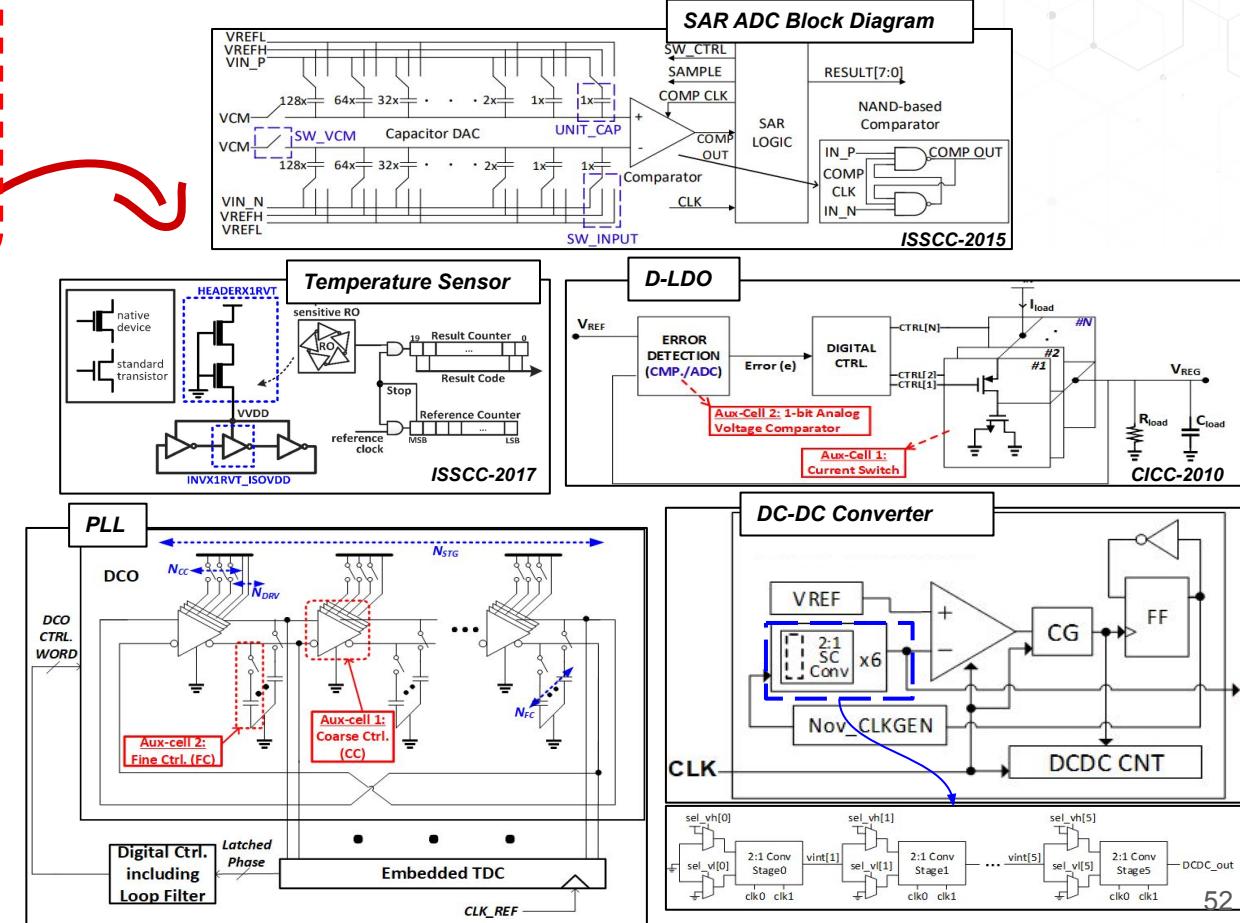
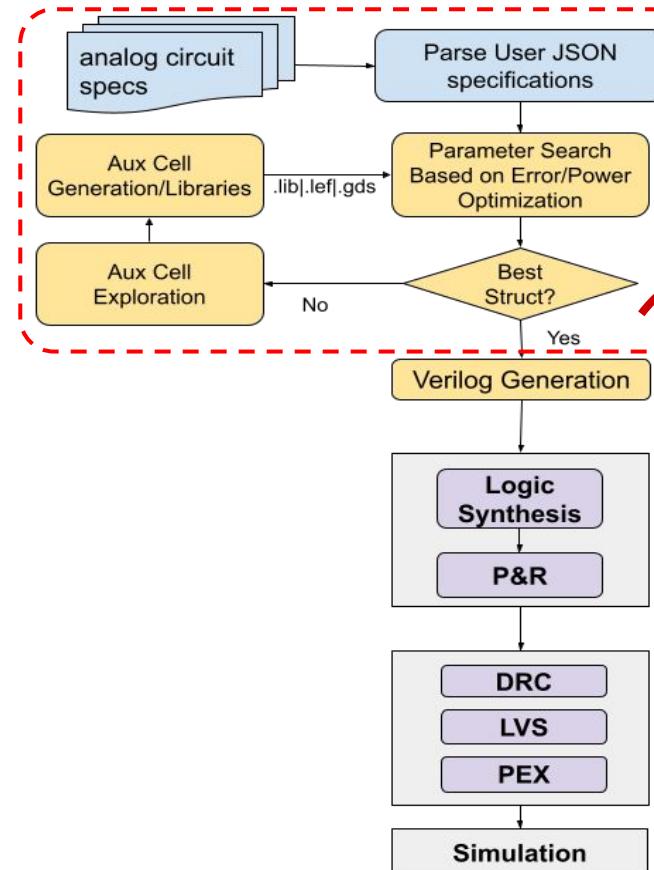


- **Analog design flow**
*Significant number of **manual** and **custom** steps.*
- **Digital** design (*grid-based*) flow
*Almost **entirely automated**.*

Generated Analog *into* Digital design flow

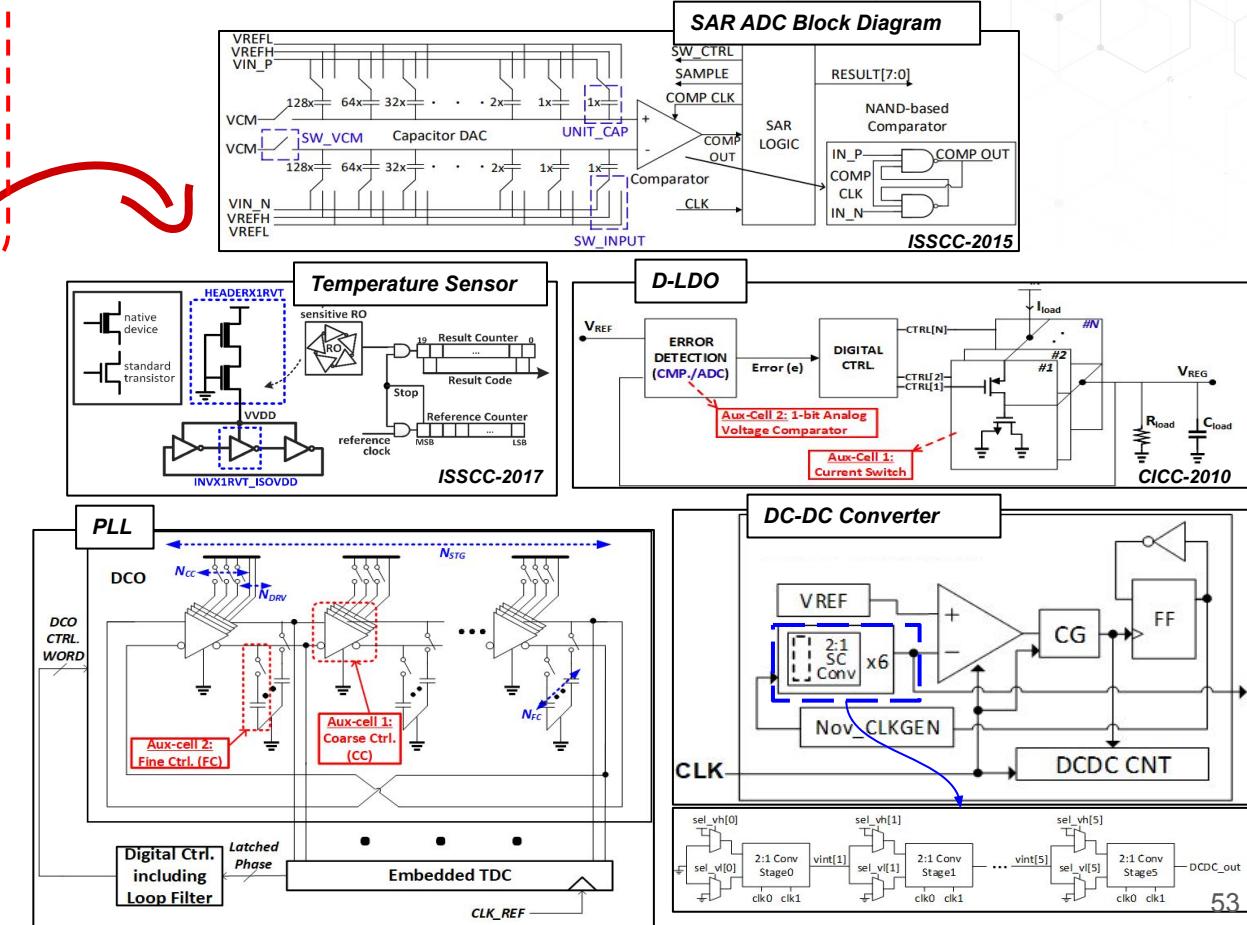
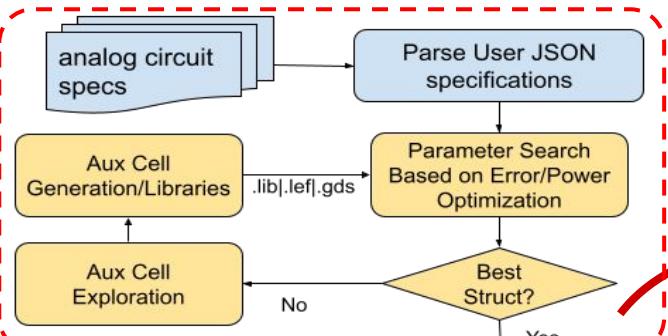
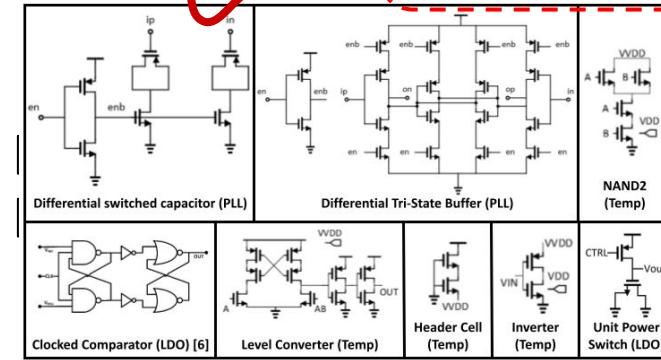
FASoC Generator

Automated
 Manual/Custom



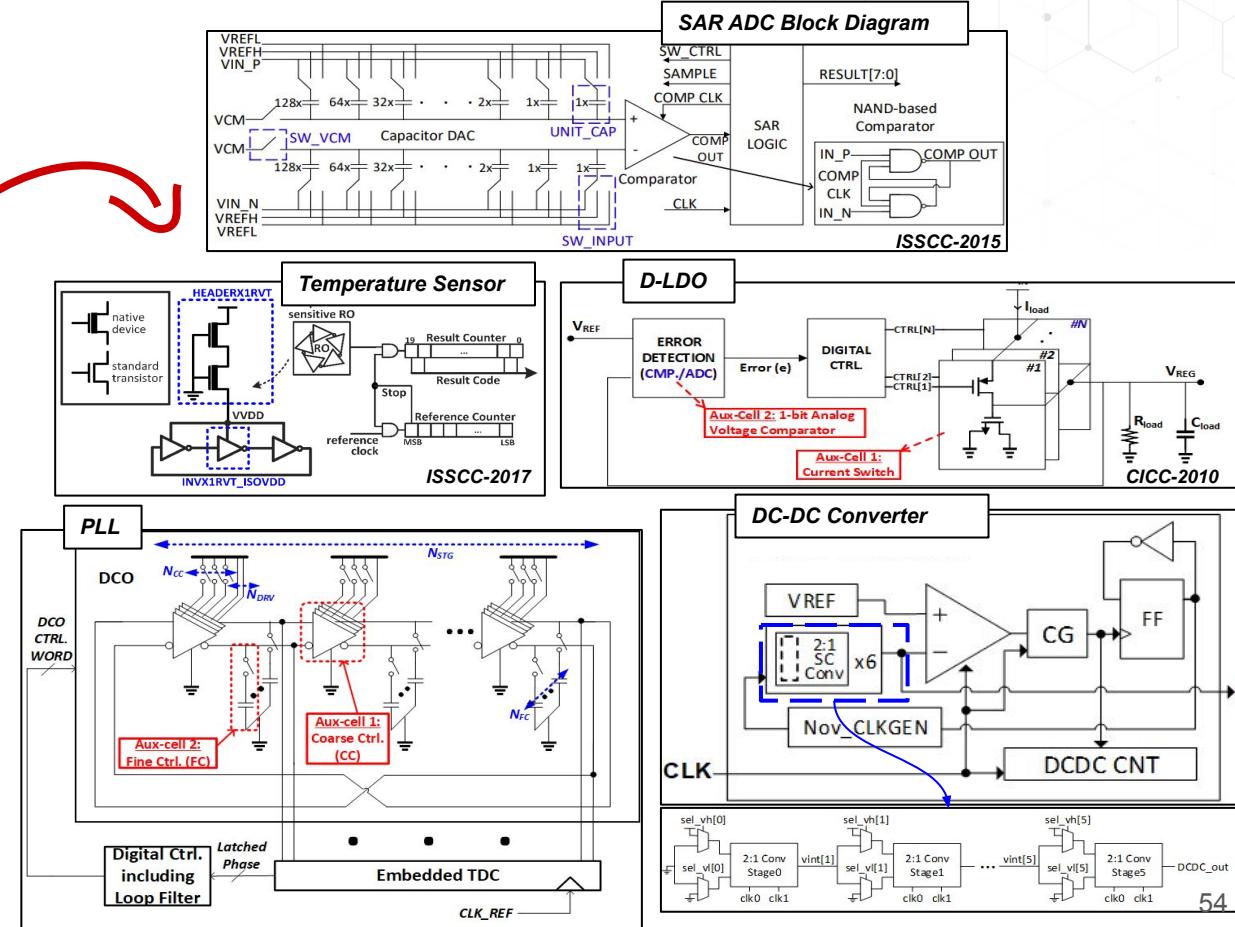
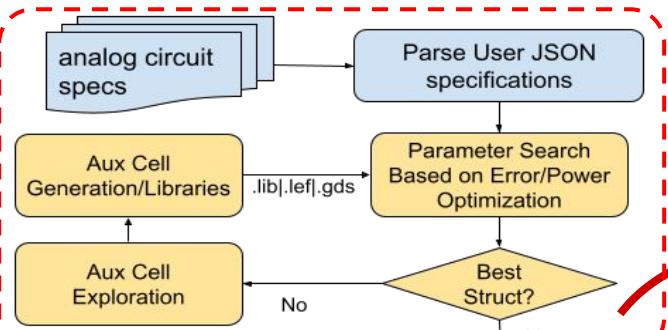
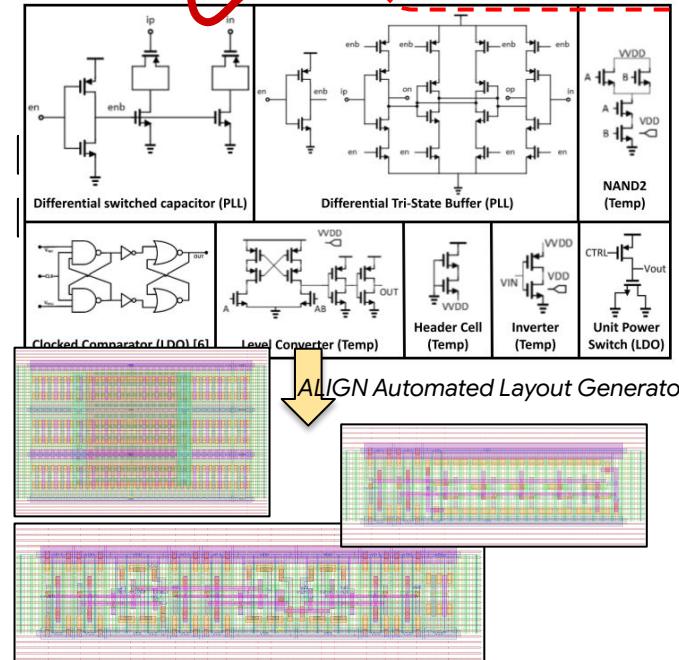
Generated Analog *into* Digital design flow

**FASoC
Generator**



Generated Analog *into* Digital design flow

FASoC Generator



Initially only proprietary design flow

